



Numonyx™ Wireless Flash Memory (W18/W30 SCSP)

32WQ and 64WQ Family with Asynchronous RAM

Datasheet

Product Features

- Device Architecture
 - Flash Density: 32-Mbit, 64-Mbit
 - Async PSRAM Density: 16-Mbit, 32-Mbit
 - Top, Bottom or Dual flash parameter configuration
- Device Voltage
 - Flash VCC = 1.8 V; Flash VCCQ = 1.8 V or 3.0 V
 - RAM VCC = 1.8 V or 3.0 V
- Device Packaging
 - 88 balls (8 x 10 active ball matrix)
 - Area: 8x10 mm
 - Height: 1.2 mm to 1.4 mm
- PSRAM Performance
 - 70 ns initial access, 25 ns async page reads at 1.8 V I/O
 - 70 ns initial access async PSRAM at 1.8 V I/O
 - 70 ns initial access, 25 ns async page reads at 3.0 V I/O
- SRAM Performance
 - 70 ns initial access at 1.8 V or 3.0 V I/O
- Quality and Reliability
 - Extended Temperature: -25 °C to +85 °C
 - Minimum 100K flash block erase cycle
 - 90 nm ETOX™ IX flash technology
 - 130 nm ETOX™ VIII flash technology
- Flash Performance
 - 65 ns initial access at 1.8 V I/O
 - 70 ns initial access at 3.0 V I/O
 - 25 ns async page at 1.8 V or 3.0 V I/O
 - 14 ns sync reads (t_{CHQV}) at 1.8 V I/O
 - 20 ns sync reads (t_{CHQV}) at 3.0 V I/O
 - Enhanced Factory Programming: 3.10 μ s/Word (Typ)
- Flash Architecture
 - Read-While-Write/Erase
 - Asymmetrical blocking structure
 - 4-KWord parameter blocks (Top or Bottom)
 - 32-KWord main blocks
 - 4-Mbit partition size
 - 128-bit One-Time Programmable (OTP) Protection Register
 - Zero-latency block locking
 - Absolute write protection with block lock using F-VPP and F-WP#
- Flash Software
 - Numonyx™ Flash Data Integrator (FDI) and Common Flash Interface (CFI)

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH NUMONYX™ PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN NUMONYX'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, NUMONYX ASSUMES NO LIABILITY WHATSOEVER, AND NUMONYX DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF NUMONYX PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. Numonyx products are not intended for use in medical, life saving, life sustaining, critical control or safety systems, or in nuclear facility applications.

Numonyx B.V. may make changes to specifications and product descriptions at any time, without notice.

Numonyx B.V. may have patents or pending patent applications, trademarks, copyrights, or other intellectual property rights that relate to the presented subject matter. The furnishing of documents and other materials and information does not provide any license, express or implied, by estoppel or otherwise, to any such patents, trademarks, copyrights, or other intellectual property rights.

Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined." Numonyx reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them.

Contact your local Numonyx sales office or your distributor to obtain the latest specifications and before placing your product order.

Copies of documents which have an order number and are referenced in this document, or other Numonyx literature may be obtained by visiting Numonyx's website at <http://www.numonyx.com>.

Numonyx, the Numonyx logo, and StrataFlash are trademarks or registered trademarks of Numonyx B.V. or its subsidiaries in other countries.

*Other names and brands may be claimed as the property of others.

Copyright © 2007, Numonyx B.V., All Rights Reserved.

Contents

1.0	Introduction	6
1.1	Nomenclature	6
1.2	Conventions	7
2.0	Functional Overview	8
2.1	Block Diagram	8
2.2	Flash Memory Map and Partitioning.....	9
3.0	Package Information	10
4.0	Ballout and Signal Description	13
4.1	Signal Ballout	13
4.2	Signal Descriptions	14
5.0	Maximum Ratings and Operating Conditions	16
5.1	Absolute Maximum Ratings.....	16
5.2	Operating Conditions	16
5.3	Capacitance.....	17
6.0	Electrical Specifications	18
6.1	DC Characteristics.....	18
7.0	AC Characteristics	20
7.1	Flash AC Characteristics	20
7.2	SRAM AC Characteristics	20
7.3	PSRAM AC Characteristics.....	22
7.4	Device AC Test Conditions	27
8.0	Flash Power Consumption	28
9.0	Device Operation	29
9.1	Bus Operations	29
10.0	Flash Command Definitions	33
11.0	Flash Read Operations	33
12.0	Flash Program Operations	33
13.0	Flash Erase Operations	33
14.0	Flash Security Modes	33
15.0	Flash Read Configuration Register	33
16.0	SRAM Operations	34
16.1	Power-up Sequence and Initialization.....	34
16.2	Data Retention Mode	34
17.0	PSRAM Operations	36
17.1	Power-Up Sequence and Initialization.....	36
17.1.1	16Mbit PSRAM Power-Up Sequence (Non-Page Mode).....	36
17.2	Standby Mode/ Deep Power-Down Mode.....	37
17.3	PSRAM Special Read and Write Constraints	37
A	Write State Machine	38
B	Common Flash Interface	38
C	Flash Flowcharts	38
D	Additional Information	38

E Ordering Information (Active Line Items)39
F Ordering Information (Retired Line Items)40

Revision History

Date	Revision	Description
June 2003	-001	Initial release
September 2003	-002	Changed PSRAM Read values. Added new Transient Equivalent Testing Load Circuit figure. General text edits.
May 2004	-006	Reformatted the datasheet and moved sections around according to the new layout.
August 2004	-007	Added 90 nm product information. Added line items. Added DC and AC specs for the new line items and edits to related sections.
January 2005	-008	Added line items. Added 32WQ product information.
June 2005	-009	Added line items.
October 2005	-010	Removed Power-up sequence from Section 16; Added 70ns PSRAM (non-page mode) specification Updated Ordering Information
June 2007	-011	Updated Ordering information with active and retired line items. Updated AC spec & power-up specs for 38F2030W0YxQE & 38F2040W0YxQE
August 2007	-012	Rempved 38F2030W0YxQE & 38F2040W0YxQE Line Items Updated ordering information
November 2007	13	Applied Numonyx branding.

1.0 Introduction

This document contains information pertaining to the products in the Numonyx™ Wireless Flash Memory (W18/W30 SCSP) family with asynchronous RAM. The W18/W30 SCSP 32WQ and 64WQ families offer a wide variety of stacked combinations that include single flash die, two flash die, flash + PSRAM, and flash + SRAM options. This document provides information where this SCSP family differs from the Numonyx Wireless Flash Memory (W18/W30) discrete device.

Refer to the discrete datasheets *Numonyx™ Wireless Flash Memory (W18) Datasheet* (order number 290701) and *Numonyx™ Wireless Flash Memory (W30) Datasheet* (order number 290702) for flash product details not included in this SCSP datasheet.

The Numonyx Wireless Flash Memory (W18/W30 SCSP) family offers various flash plus static RAM combinations in a common package footprint. The flash memory features 1.8 V low-power operations with flexible, multi-partition, dual-operation Read-While-Write / Read-While-Erase, asynchronous, and synchronous reads. This SCSP device integrates up to two flash die, and one PSRAM or SRAM die in a low-profile package compatible with other SCSP families with QUAD+ ballout.

1.1 Nomenclature

0x	Hexadecimal prefix
0b	Binary prefix
Byte	8 bits
CFI	Common Flash Interface
CUI	Command User Interface
DU	Don't Use
ETOX	EPROM Tunnel Oxide
FDI	Numonyx™ Flash Data Integrator (software solution)
K(noun)	1 thousand
Kb	1024 bits
KB	1024 bytes
Kword	1024 words
M (noun)	1 million
Mb	1,048,576 bits
MB	1,048,576 bytes
OTP	One-Time Programmable
PLR	Protection Lock Register
PR	Protection Register
PRD	Protection Register Data
RCR	Read Configuration Register

RFU	Reserved for Future Use
SCSP	Stacked Chip Scale Package
SR	Status Register
SRD	Status Register Data
Word	16 bits
WSM	Write State Machine

1.2 Conventions

Group Membership Brackets: Square brackets are used to designate group membership or to define a group of signals with a similar function, such as A[21:1] and SR[4,1].

VCC vs. V_{CC} : When referring to a signal or package-connection name, the notation used is VCC, etc. When referring to a timing or electrical level, the notation used is subscripted such as V_{CC} , etc.

Device: This term is used interchangeably throughout this document to denote either a particular die, or the combination of multiple die within a single package.

F[3:1]-CE#, F[2:1]-OE#: This is the method used to refer to more than one chip-enable or output enable at the same time. When each is referred to individually, the reference will be F1-CE# and F1-OE# (for die #1), and F2-CE# and F2-OE# (for die #2).

F-VCC, P-VCC or S-VCC: When referencing flash memory signals or timings, the notation used is F-VCC or F- V_{CC} , respectively. When the reference is to PSRAM signals or timings, the notation is prefixed with "P-" (e.g., P-VCC, P- V_{CC}). When referencing SRAM signals or timings, the notation is prefixed with "S-" (e.g., S-VCC or S- V_{CC}). P-VCC and S-VCC are RFU for stacked combinations that do not include PSRAM or SRAM.

R-OE#, R-LB#, R-UB#, R-WE#: These are used to identify RAM OE#, LB#, UB#, WE# signals, and are usually shared between 2 or more RAM die. R-OE#, R-LB#, R-UB# and R-WE are RFU for stacked combinations that do not include PSRAM or SRAM.

2.0 Functional Overview

This section provides an overview of the features and capabilities of the Numonyx Wireless Flash Memory (W18/W30 SCSP) family with asynchronous RAM device.

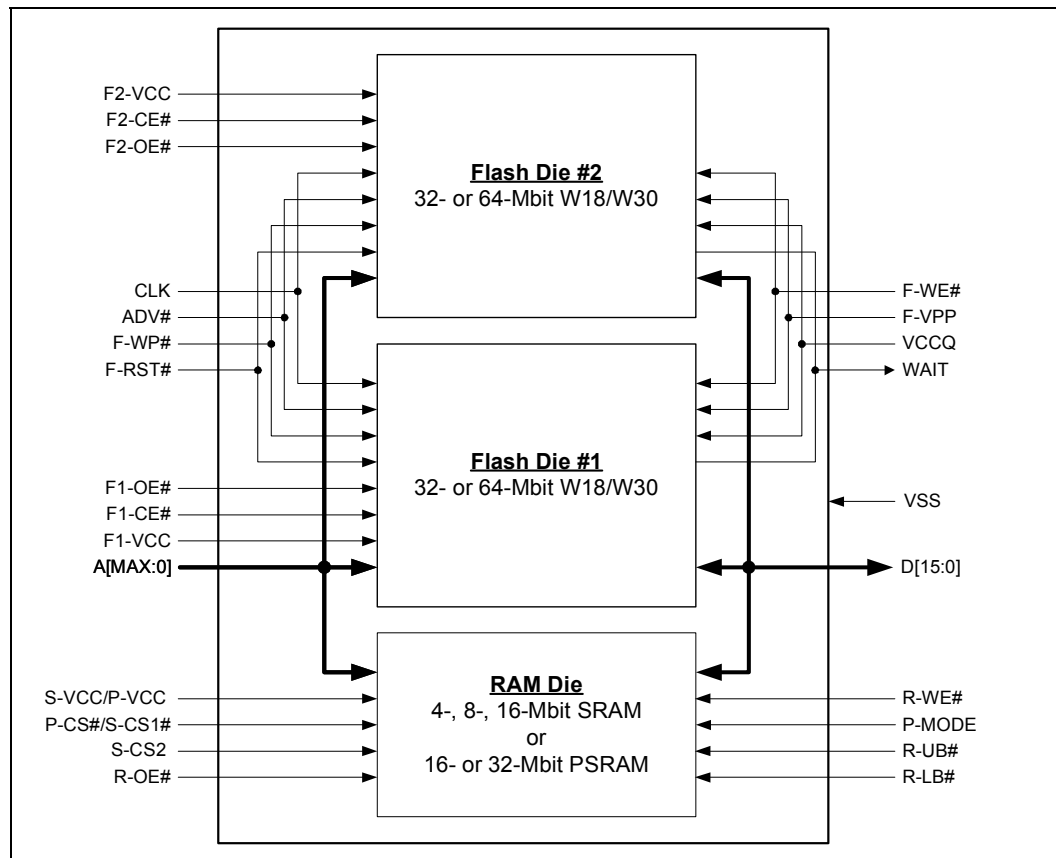
The W18/W30 SCSP device provides flash + RAM die combinations. Products range from single flash die, two flash die, flash + PSRAM, or flash + SRAM. You can choose a W18 SCSP device or a W30 SCSP device with SRAM or PSRAM offered with the same package footprint and signal ballout.

2.1 Block Diagram

Show here are all internal package connections for the SCSP family with multiple die. See [Table 21, "Ordering Information on Active Line Items" on page 40](#) for valid combinations of flash and RAM die. Unused connections on combinations with less than three die are reserved and should not be used.

Please contact your local Numonyx representative for details regarding any reserved or RFU pins.

Figure 1: Block Diagram



2.2 Flash Memory Map and Partitioning

Consult the latest *Numonyx™ Wireless Flash Memory (W18) Datasheet* (order number 290701) and the *Numonyx™ Wireless Flash Memory (W30) Datasheet* (order number 290702), for individual flash die memory map and partitioning information.

Table 1 and **Table 2** show memory map and partitioning information for dual-flash memory die configurations. Flash Die #1 (with F1-CE# as its Chip Select) is configured as a bottom parameter while Flash Die #2 (with F2-CE# as its Chip Select) is configured as top parameter.

3.0 Package Information

The following two packages are offered with the 32WQ and 64WQ Family.

Figure 2: Mechanical Specifications for 1- or 2-Die SCSP Device (8x10x1.2 mm)

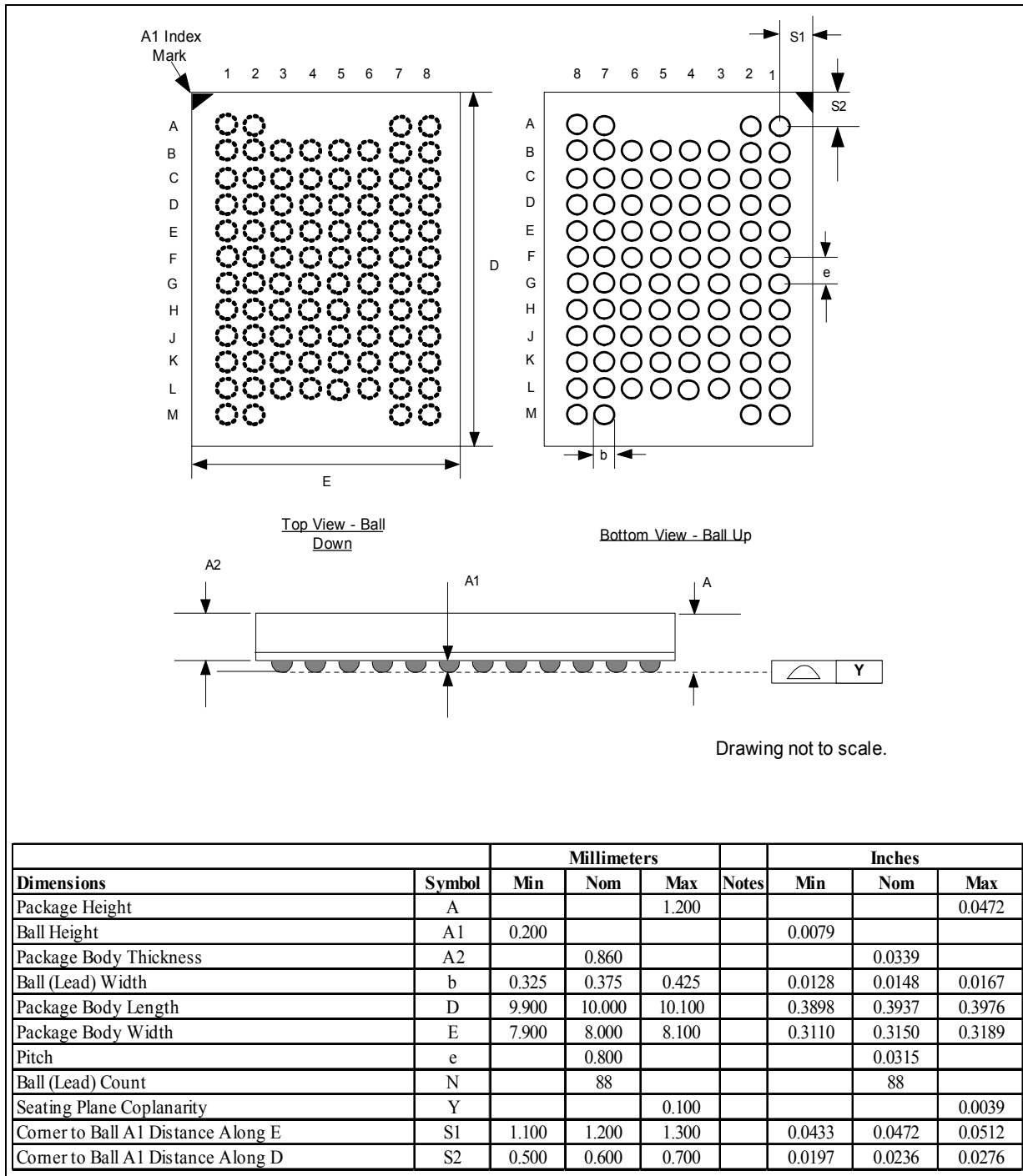


Figure 3: Mechanical Specifications for Triple-Die SCSP Device (8x10x1.4 mm)

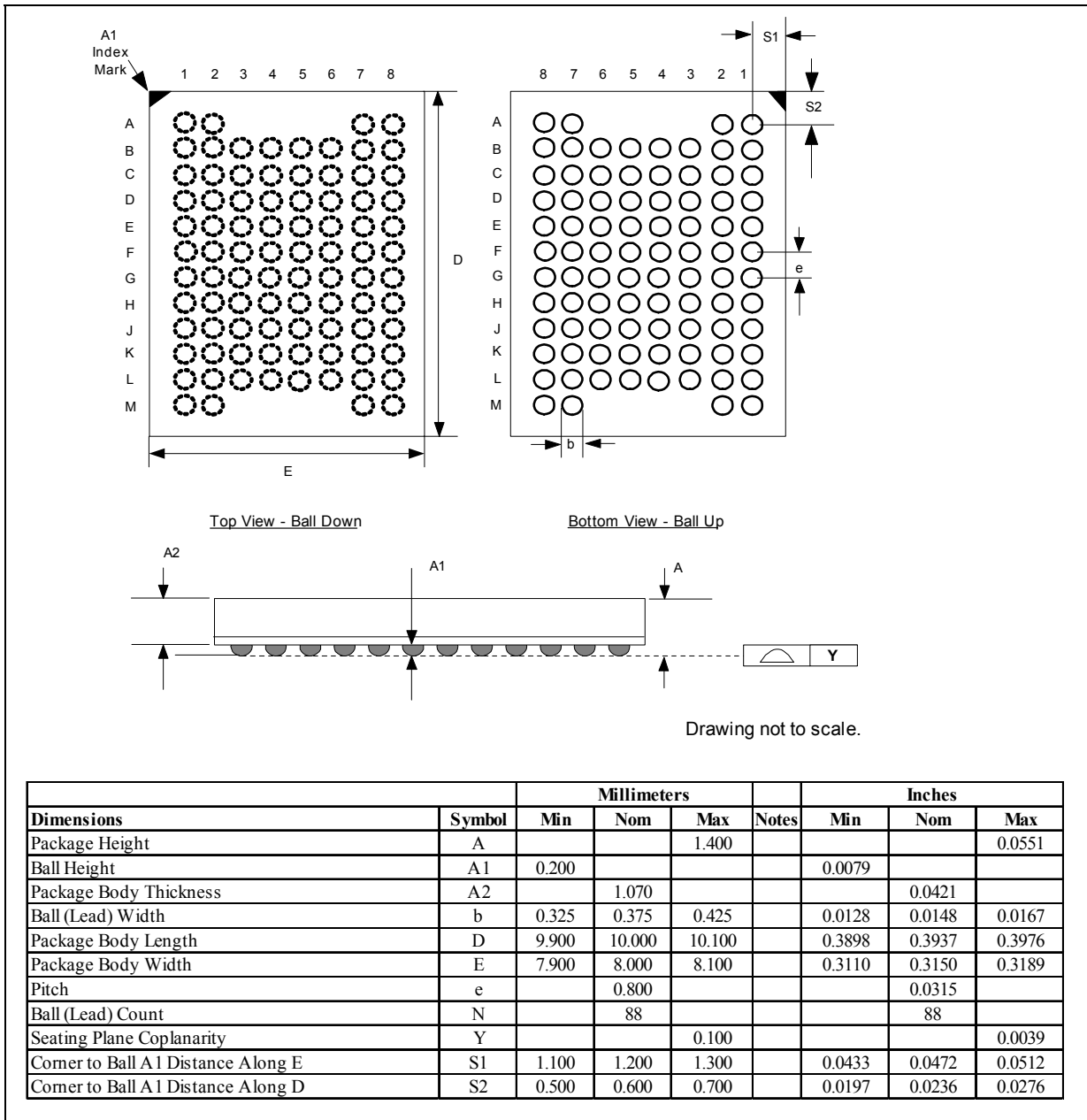


Table 1: 64-Mbit Flash + 32-Mbit Flash Die W18/W30 SCSP Memory Map and Partitioning

Partitioning			Block Size (KW)	Block #	Address Range
Flash Die #2 (32-Mbit) Top Parameter	Parameter Partition	Partition 0	4	63-70	1F8000-1FFFFFF
			32	56-62	1C0000-1F7FFF
	Main Partitions	Partition 1	32	48-55	180000-1BFFFF
		Partition 2	32	40-47	140000-17FFFF
		Partition 3	32	32-39	100000-13FFFF
		Partitions 4-7	32	0-31	000000-0FFFFF
Flash Die #1 (64-Mbit) Bottom Parameter	Main Partitions	Partitions 8-15	32	71-134	200000-3FFFFFF
		Partitions 4-7	32	39-70	100000-1FFFFFF
		Partition 3	32	31-38	0C0000-0FFFFF
		Partition 2	32	23-30	080000-0BFFFF
		Partition 1	32	15-22	040000-07FFFF
	Parameter Partition	Partition 0	32	8-14	008000-03FFFF
			4	0-7	000000-007FFF

Table 2: 64-Mbit Dual-Flash Die W18/W30 SCSP Memory Map and Partitioning

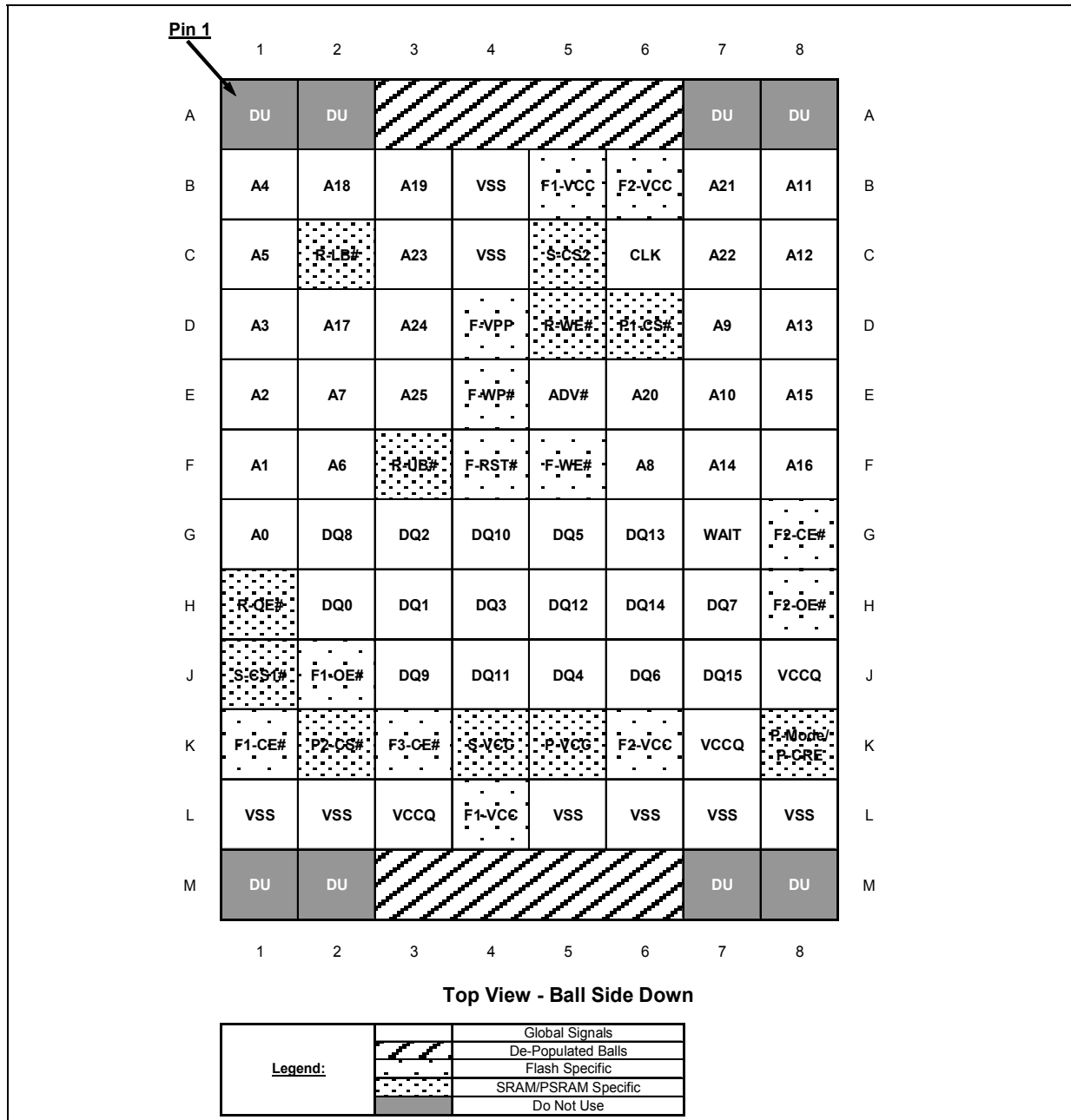
Partitioning			Block Size (KW)	Block #	Address Range
Flash Die #2 (64-Mbit) Top Parameter	Parameter Partition	Partition 0	4	127-134	3F8000-3FFFFFF
			32	120-126	3C0000-3F7FFF
	Main Partitions	Partition 1	32	112-119	380000-3BFFFF
		Partition 2	32	104-111	340000-37FFFF
		Partition 3	32	96-103	300000-33FFFF
		Partitions 4-7	32	64-95	200000-2FFFFFF
		Partitions 8-15	32	0-63	000000-1FFFFFF
Flash Die #1 (64-Mbit) Bottom Parameter	Main Partitions	Partitions 8-15	32	71-134	200000-3FFFFFF
		Partitions 4-7	32	39-70	100000-1FFFFFF
		Partition 3	32	31-38	0C0000-0FFFFF
		Partition 2	32	23-30	080000-0BFFFF
		Partition 1	32	15-22	040000-07FFFF
	Parameter Partition	Partition 0	32	8-14	008000-03FFFF
			4	0-7	000000-007FFF

4.0 Ballout and Signal Description

4.1 Signal Ballout

Figure 4 shows the 32WQ and 64WQ W18/W30 SCSP family 88-ball (8x10 active ball matrix) device.

Figure 4: 88-Ball (8x10 Active Ball Matrix) QUAD+ Ballout



4.2 Signal Descriptions

Table 3: Signal Descriptions (Sheet 1 of 2)

Symbol	Type	Name and Function
A[21:0]	Input	<p>ADDRESS INPUTS: Inputs for all die addresses during read and write operations. Addresses are internally latched during write operations.</p> <ul style="list-style-type: none"> • 4-Mbit: A[17:0] • 8-Mbit: A[18:0] • 16-Mbit: A[19:0] • 32-Mbit: A[20:0] • 64-Mbit: A[21:0] <p>A0 is the lowest-order word address. A[25:22] denote high-order addresses reserved for future device densities</p>
D[15:0]	Input/Output	<p>DATA INPUTS/OUTPUTS: Inputs data and commands during write cycles; outputs data during read cycles. Data signals float when the device or its outputs are deselected. Data are internally latched during writes.</p>
CLK	Input	<p>FLASH CLOCK: CLK synchronizes the selected flash die to the memory bus frequency in synchronous-read mode. During synchronous read operations, the initial address is latched on the rising edge of ADV#, or the rising/ falling edge of CLK when ADV# is low, whichever occurs first. CLK is only used in synchronous-read mode. Refer to the flash discrete product datasheet for information on how to use this signal in asynchronous-read mode.</p>
ADV#	Input	<p>FLASH ADDRESS VALID: Low-true; During synchronous read operations, the initial address is latched on the rising edge of ADV#, or the rising/ falling edge of CLK when ADV# is low, whichever occurs first. Refer to the flash discrete product datasheet for information on how to use this signal in asynchronous-read mode.</p>
WAIT	Output	<p>FLASH WAIT: When asserted, WAIT indicates invalid data from the selected flash die on D[15:0]. WAIT is High-Z whenever the flash die is deselected ($CE\# = V_{IL}$). WAIT is not gated by OE#. WAIT is only used in synchronous array-read mode. Refer to the flash discrete product datasheet for information on how to use this signal in asynchronous-read mode.</p>
F[3:1]-CE#	Input	<p>FLASH CHIP ENABLE: Low-true; CE#-low selects the associated flash memory die. When asserted, flash internal control logic, input buffers, decoders, and sense amplifiers are active. When deasserted, the associated flash die is deselected; power is reduced to standby levels, data and WAIT outputs are placed in High-Z. F1-CE# selects flash die #1; F2-CE# selects flash die #2 and is RFU on combinations with only one flash die. F3-CE# selects flash die #3 and is RFU on SCSP combinations with only one or two flash die.</p>
S-CS1# S-CS2	Input	<p>SRAM CHIP SELECTS: When both SRAM chip selects are asserted, SRAM internal control logic, input buffers, decoders, and sense amplifiers are active. When either/both SRAM chip selects are deasserted ($S-CS1\# = V_{IH}$ and/or $S-CS2 = V_{IL}$), the SRAM is deselected and its power is reduced to standby levels. S-CS1# and S-CS2 are only available on SCSP combinations with SRAM die.</p>
P[2:1]-CS#	Input	<p>PSRAM CHIP SELECTS: Low-true; When asserted, PSRAM internal control logic, input buffers, decoders, and sense amplifiers are active. When deasserted, the PSRAM is deselected and its power is reduced to standby levels. P1-CS# selects PSRAM die #1 and is available only on SCSP combinations with PSRAM die. This ball is RFU on SCSP combinations without PSRAM. P2-CS# selects PSRAM die #2 and is available only on SCSP combinations with two PSRAM die. This ball is RFU on SCSP combinations without PSRAM or with a single PSRAM.</p>
F[2:1]-OE#	Input	<p>FLASH OUTPUT ENABLE: Low-true; OE#-low enables the flash output buffers. OE#-high disables the flash output buffers, and places the flash outputs in High-Z. F1-OE# controls the outputs of flash die #1; F2-OE# controls the outputs of flash die #2 and #3, and is available only on SCSP combinations with two or three flash die and is RFU on SCSP combinations with only one flash die.</p>
R-OE#	Input	<p>RAM OUTPUT ENABLE: Low-true; R-OE#-low enables the RAM output buffers. R-OE#-high disables the RAM output buffers, and places the RAM outputs in High-Z. R-OE# is only available on SCSP combinations with RAM die.</p>

Table 3: Signal Descriptions (Sheet 2 of 2)

Symbol	Type	Name and Function
R-UB# R-LB#	Input	RAM UPPER/ LOWER BYTE ENABLES: Low-true; During RAM reads, R-UB#-low enables the RAM high-order bytes on D[15:8], and R-LB#-low enables the RAM low-order bytes on D[7:0]. R-UB# and R-LB# are only available on SCSP combinations with either SRAM die or PSRAM die.
F-WE#	Input	FLASH WRITE ENABLE: Low-true; WE# controls writes to the selected flash die. Address and data are latched on the rising edge of WE#.
R-WE#	Input	RAM WRITE ENABLE: Low-true; R-WE# controls writes to the RAM die. R-WE# is only available on SCSP combinations with RAM die.
F-WP#	Input	FLASH WRITE PROTECT: Low-true; WP# enables/disables the lock-down protection mechanism of the flash die. WP#-low enables the lock-down mechanism- locked down blocks cannot be unlocked with software commands. WP#-high disables the lock-down mechanism, allowing locked down blocks to be unlocked with software commands.
F-RST#	Input	FLASH RESET: Low-true; RST#-low initializes flash internal circuitry and disables flash operations. RST#-high enables flash operation. Exit from reset places the flash in asynchronous read array mode.
F-VPP F-VPEN	Power	FLASH PROGRAM/ ERASE POWER: A valid F-V _{pp} voltage on this ball enables flash program/erase operations. Flash memory array contents cannot be altered when $F-V_{pp}(V_{PEN}) \leq V_{PPLK}(V_{PENLK})$. Erase/program operations at invalid F-V _{pp} (V _{PEN}) voltages should not be attempted. Refer to the flash discrete product datasheet for additional details. F-V _{PEN} (Erase/Program/Block Lock Enables) is not available for W18/W30 products.
P-MODE	Input	PSRAM MODE: Low-true; P-MODE is used to enter/exit low power mode. Low power mode is not applicable to 38F2020W0ZTQ1, 38F2020W0ZBQ1, 38F2030W0YTQ1, 38F2030W0YBQ1, 38F2030W0ZTQ2, 38F2030W0ZBQ2, 38F1030W0ZTQ0, 38F1030W0ZBQ0. P-Mode is only available on SCSP combinations with PSRAM die.
F[2:1]-VCC	Power	FLASH LOGIC POWER: F1-VCC supplies power to the core logic of flash die #1; F2-VCC supplies power to the core logic of flash die #2 and #3. Write operations are inhibited when $F-V_{CC} \leq V_{LKO}$. Device operations at invalid F-V _{CC} voltages should not be attempted. F2-VCC is only available on SCSP combinations with two or three flash die, and is RFU on SCSP combinations with only one flash die.
S-VCC	Power	SRAM Power Supply: Supplies power to the SRAM die. S-VCC is only available on SCSP combinations with SRAM die.
P-VCC	Power	PSRAM Power Supply: Supplies power to the PSRAM die. P-VCC is only available on SCSP combinations with PSRAM die.
VCCQ	Power	FLASH OUTPUT-BUFFER POWER: Supplies power for the I/O output buffers.
VSS	Power	Ground: Connect to ground. Do not float any VSS connection.
RFU	—	Reserved for Future Use: Reserve for future device functionality/ enhancements.
DU	—	Don't Use: Do not connect to any other signal, or power supply; must be left floating.

5.0 Maximum Ratings and Operating Conditions

5.1 Absolute Maximum Ratings

Warning: Stressing the device beyond the “Absolute Maximum Ratings” may cause permanent damage. These are stress ratings only.

NOTICE: This document contains information available at the time of its release. The specifications are subject to change without notice. Verify with your local Numonyx sales office that you have the latest datasheet before finalizing a design.

Table 4: Absolute Maximum Ratings

Parameter		Min	Max	Unit	Notes
Temperature under Bias Extended		-25	+85	°C	7
Storage Temperature		-55	+125	°C	
Voltage On Any Signal (except F[2:1]-V _{CC} , V _{CCQ} , F-V _{PP} , S-V _{CC} and P-V _{CC})	1.8 V I/O	-0.2	+2.45	V	1,2,3
	3.0 V I/O	-0.2	+3.6	V	2,3
F[2:1]-V _{CC} Voltage		-0.5	+2.45	V	2,3
V _{CCQ} , S-V _{CC} and P-V _{CC} Voltage	1.8 V I/O	-0.2	+2.45	V	1,2,3
	3.0 V I/O	-0.2	+3.6	V	2,3
F-V _{PP} Voltage		-0.2	+14.0	V	2,3,4,5
I _{SH} Output Short Circuit Current		-	100	mA	6

Notes:

- 90 nm is only avail with the 1.8 V I/O.
- All Specified voltages are relative to V_{SS}. Minimum DC voltage is -0.2 V on input/output signals, -0.2 V on F[2:1]-V_{CC} and F-V_{PP} signals. For 90 nm devices, during transitions, this level may overshoot to -1.5 V for periods < 20 ns, during transitions, may overshoot to F-V_{CC} + 1.5 V for periods < 20 ns.
- All Specified voltages are relative to V_{SS}. Minimum DC voltage is -0.2 V on input/output signals, -0.2 V on F[2:1]-V_{CC} and F-V_{PP} signals. For 130 nm devices, during transitions, this level may overshoot to -2 V for periods < 20 ns, during transitions, may overshoot to F-V_{CC} + 2 V for periods < 20 ns.
- Maximum DC voltage on F-V_{PP} may overshoot to +14.0 V for periods < 20 ns.
- F-V_{PP} program voltage is normally V_{ppL}. The maximum DC voltage on F-V_{PP} may overshoot to +14 V for periods < 20 ns. F-V_{PP} can be V_{ppH} for 1000 erase cycles on main blocks, 2500 cycles on parameter blocks.
- Output shorted for no more than one second. No more than one output shorted at a time.
- Devices available with -30° C temperature specifications are: 38F2020W0ZTQ1, 38F2020W0ZBQ1, 38F2030W0YTQ1, 38F2030W0YBQ1, 38F2030W0ZTQ2, 38F2030W0ZBQ2, 38F1030W0ZTQ0, 38F1030W0ZBQ0, 38F2030W0YTQF, 38F2030W0YBQF, 38F2040W0YTQF, 38F2040W0YBQF

5.2 Operating Conditions

Warning: Operation beyond the “Operating Conditions” is not recommended and extended exposure beyond the “Operating Conditions” may affect device reliability.

Table 5: Operating Conditions (Sheet 1 of 2)

Symbol	Parameter	Flash + Flash		Flash + SRAM		Flash + PSRAM		Unit	Notes
		Min	Max	Min	Max	Min	Max		
T _C	Operating Temperature	-25	+85	-25	+85	-25	+85	°C	2
F-V _{CC}	Flash Supply Voltage	1.7	1.95	1.7	1.95	1.7	1.95	V	

Table 5: Operating Conditions (Sheet 2 of 2)

V_{CCQ} S-V_{CC} P-V_{CC}	Flash I/O Voltage	3.0 V I/O	2.2	3.3	2.2	3.3	2.7	3.1	V	
	PSRAM and SRAM Supply Voltage	1.8 V I/O	1.7	1.95	1.7	1.95	1.8	1.95	V	
V_{PPL}	Flash Program Logic Level		0.9	1.95	0.9	1.95	0.9	1.95	V	
V_{PPH}	Flash Factory Program Voltage		11.4	12.6	11.4	12.6	11.4	12.6	V	1
Note:										
1. F-V _{PP} is normally V _{PPL} . F-V _{PP} can be connected to 11.4 V–12.6 V for 1000 cycles on main blocks for extended temperatures and 2500 cycles on parameter blocks at extended temperature.										
2. Devices available with -30° C temperature specifications are: 38F2020W0ZTQ1, 38F2020W0ZBQ1, 38F2030W0YTQ1, 38F2030W0YBQ1, 38F2030W0ZTQ2, 38F2030W0ZBQ2, 38F1030W0ZTQ0, 38F1030W0ZBQ0, 38F2030W0YTQF, 38F2030W0YBQF, 38F2040W0YTQF, 38F2040W0YBQF										

5.3 Capacitance

NOTICE: Refer to the *Numonyx™ Wireless Flash Memory (W18) Datasheet* (order number 290701) and *Numonyx™ Wireless Flash Memory (W30) Datasheet* (order number 290702) for flash capacitance details. For SCSP products with two flash die, flash capacitances for each of the flash die need to be considered accordingly.

Table 6: SRAM, PSRAM Capacitance

Symbol	Parameter	Typ	Unit	Condition
C_{IN}	Input Capacitance	10	pF	V _{IN} = 0.0 V, T _c = 25 °C, f = 1 MHz
C_{OUT}	Output Capacitance	10	pF	V _{OUT} = 0.0 V, T _c = 25 °C, f = 1 MHz

6.0 Electrical Specifications

6.1 DC Characteristics

SRAM and PSRAM DC characteristics are shown in [Table 7](#) and [Table 8](#). Refer to the *Numonyx Wireless Flash Memory (W18) Datasheet* (order number 290701) and the *Numonyx Wireless Flash Memory (W30) Datasheet* (order number 290702) for flash DC characteristics.

Table 7: SRAM DC Characteristics

Parameter	Description	Test Conditions	1.8 V SRAM		3.0 V SRAM		Unit	
			Min	Max	Min	Max		
S-V _{CC}	Voltage Range		1.7	1.95	2.2	3.3	V	
V _{DR}	V _{CC} for Data Retention		1.0	–	1.5	–	V	
I _{CC}	Operating Current at min cycle time	I _{IO} = 0 mA	4M	–	25	–	45	mA
			8M	–	35	–	50	
			16M	–	40	–	55	
I _{CC2}	Operating Current at max cycle time (1 μs)	I _{IO} = 0 mA	4M	–	4	–	10	mA
			8M	–	6	–	10	
			16M	–	10	–	15	
I _{SB}	Standby Current	S-CS1# ≥ S-V _{CC} -0.2V or S-CS2 ≤ V _{SS} +0.2V Address/Data toggling at minimum cycle time	4M	–	12	–	15	μA
			8M	–	20	–	25	
			16M	–	30	–	45	
I _{DR}	Current in Data Retention mode	1.8 V SRAM: S-V _{CC} = 1.0 V 3.0 V SRAM: S-V _{CC} = 1.5 V	4M	–	6	–	5	μA
			8M	–	10	–	12	
			16M	–	18	–	15	
V _{OH}	Output HIGH Voltage	I _{OH} = -100 μA	S-V _{CC} - 0.15	–	S-V _{CC} - 0.1	–	V	
V _{OL}	Output LOW Voltage	I _{OL} = 100 μA, V _{CCMIN}	-0.1	0.2	-0.1	0.1	V	
V _{IH}	Input HIGH Voltage		S-V _{CC} - 0.4	S-V _{CC} + 0.2	S-V _{CC} - 0.4	S-V _{CC} + 0.2	V	
V _{IL}	Input LOW Voltage		-0.2	0.4	-0.2	0.6	V	
I _{OH}	Output HIGH Current		–	–	–	–	mA	
I _{OL}	Output LOW Current		–	–	–	–	mA	
*I _{IL}	Input Leakage Current	-0.2 < V _{IN} < S-V _{CC} + 0.2 V	-1	+1	-1	+1	μA	
*I _{LDR}	Input Leakage Current in Data Retention Mode	-0.2 < V _{IN} < S-V _{CC} + 0.2 V S-V _{CC} = V _{DR}	-1	+1	-1	+1	μA	

* Input leakage currents include Hi-Z output leakage for bi-directional buffers with tri-state outputs.

Table 8: PSRAM DC Characteristics

Parameter	Description	Test Conditions	1.8 V PSRAM		3.0 V PSRAM		Unit	Notes	
			Min	Max	Min	Max			
V _{CC}	Voltage Range		1.8	1.95	2.7	3.1	V		
I _{CC}	Operating Current at min cycle time	I _{IO} = 0 mA	8M	-	-	-	30	mA	2
			16M	-	30	-	35		
			16M	-	20	-	-	mA	3
			32M	-	35	-	45		
I _{CC2}	Operating Current at max cycle time (1 μs)	I _{IO} = 0 mA	8M	-	-	-	5	mA	2
			16M	-	5	-	7		
			32M	-	-	-	7		
I _{SB}	Standby Current	P-CS# ≥ P-V _{CC} - 0.2V, All inputs stable (either high or low)	8M	-	-	-	80	μA	2, 4
			16M	-	100	-	100		
		P-CS# ≥ P-V _{CC} - 0.2V or P-Mode ≥ P-V _{CC} - 0.2V Address/Data toggling at minimum cycle time	16M	-	-	-	85	μA	2, 5
			32M	-	100	-	100		
I _{sbd}	Deep Power-Down	P-Mode ≤ 0.2 V	16M	-	-	-	10	μA	2, 4
			32M	-	30	-	10		
V _{OH}	Output HIGH Voltage	I _{OH} = -0.5 mA	0.8P - V _{CC}	-	2.4	-	V	4	
		I _{OH} = -0.1 mA	1.4	-	P-V _{CC} - 0.3	-	V	5	
V _{OL}	Output LOW Voltage	I _{OL} = 1 mA,	-	0.2P - V _{CC}	-	0.4	V	4	
		I _{OL} = 0.1 mA, V _{CCmin}	-0.1	0.2	-0.1	0.3	V	5	
V _{IH}	Input HIGH Voltage		0.8P - V _{CC}	P-V _{CC} + 0.3	P-V _{CC} - 0.3	P-V _{CC} + 0.2	V	4	
			P-V _{CC} - 0.3	P-V _{CC} + 0.2	P-V _{CC} - 0.4	P-V _{CC} + 0.2	V	5	
V _{IL}	Input LOW Voltage		-0.3	0.2P - V _{CC}	-0.2	0.5	V	4	
			-0.2	0.4	-0.2	0.6	V	5	
I _{IL}	Input Leakage Current	-0.2 < V _{IN} < P-V _{CC} + 0.2 V	-1	+1	-1	+1	μA	1, 2	
I _{OL}	Output Leakage Current	-0.2 < V _{IN} < P-V _{CC} + 0.2 V P-V _{CC} = V _{DR}	-1	+1	-1	+1	μA	1, 2	

Notes:

1. Input Leakage currents include Hi-Z output leakage for bi-directional buffers with tri-state outputs.
2. All currents are in RMS unless noted otherwise.
3. Applicable only to parts 38F1030W0YxQF & 38F2030W0YxQF.
4. Applicable to parts with P-Mode pin (38F2030W0ZxQ1, 38F2040W0YxQ0, 28F2240WWYxQ0).
5. Applicable to No-P-Mode (38F1030W0YxQF, 38F1030W0YxQ2, 38F1030W0ZxQ0, 38F2030W0YxQ1, 38F2030W0YxQF, 38F2030W0YxQ2, 38F2030W0YxQF, 38F2030W0ZxQ2, 38F2040W0ZxQ0).

7.0 AC Characteristics

7.1 Flash AC Characteristics

Refer to the Numonyx Wireless Flash Memory (W18) Datasheet (order number 290701) and Numonyx Wireless Flash Memory (W30) Datasheet (order number 290702)

7.2 SRAM AC Characteristics

Table 9: SRAM AC Characteristics

#	Symbol ¹	Parameter	Min	Max	Unit	Notes
R1	t_{RC}	Read Cycle Time	70	-	ns	1
R2	t_{AA}	Address to Output Delay	-	70	ns	1
R3	t_{CO1}	S-CS1# to Output Delay	-	70	ns	1
R3	t_{CO2}	S-CS2 to Output Delay	-	70	ns	1
R4	t_{OE}	R-OE# to Output Delay	-	35	ns	1
R5	t_{BA}	R-UB#, R-LB# to Output Delay	-	70	ns	1
R6	t_{LZ}	S-CS1# or S-CS2 to Output in Low-Z	5	-	ns	1,3,4
R7	t_{OLZ}	R-OE# to Output in Low-Z	0	-	ns	1,4
R8	t_{HZ}	S-CS1# or S-CS2 to Output in High-Z	0	25	ns	1,2,3,4
R9	t_{OHZ}	R-OE# to Output in High-Z	0	25	ns	1,2,4
R10	t_{OH}	Output Hold (from Address, S-CS1#, S-CS2 or R-OE# Change, whichever occurs first)	0	-	ns	1
R11	t_{BLZ}	R-UB#, R-LB# to Output in Low-Z	0	-	ns	1,4
R12	t_{BHZ}	R-UB#, R-LB# to Output in High-Z	0	25	ns	1,4

Note:

1. See [Figure 5, "AC Waveform SRAM Read Operations"](#).
2. Timings of t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
3. At any given temperature and voltage condition, t_{HZ} (Max) is less than t_{LZ} (Max) both for a given device and from device to device interconnection.
4. Sampled, but not 100% tested.

Figure 5: AC Waveform SRAM Read Operations

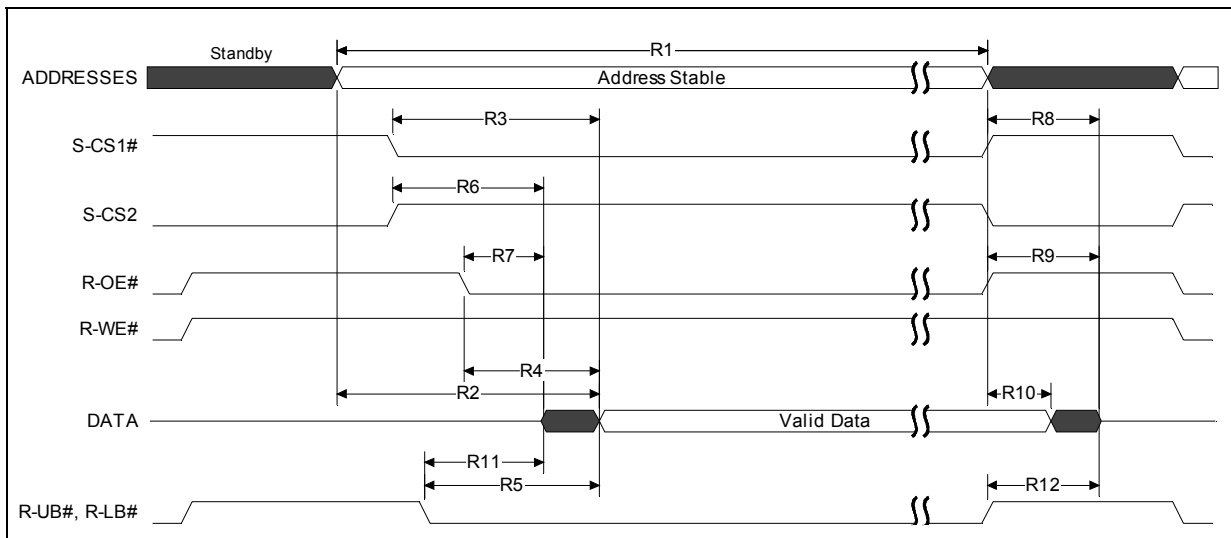


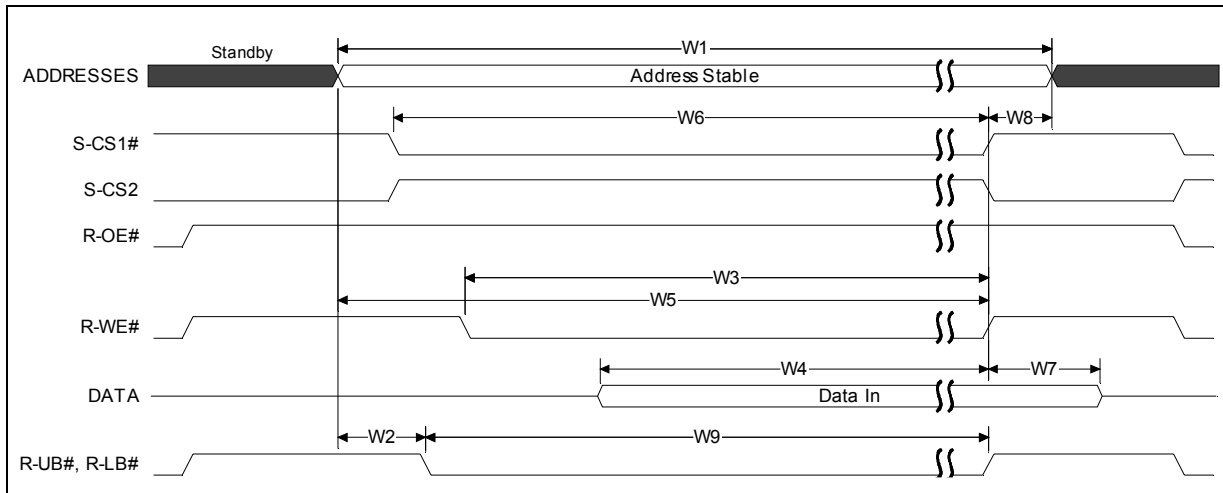
Table 10: SRAM AC Characteristics (Write)

#	Symbol ¹	Parameter	Min	Max	Unit	Notes
W1	t_{WC}	Write Cycle Time	70	-	ns	1
W2	t_{AS}	Address Setup to R-WE# (S-CS1#) and R-UB#/R-LB# Low	0	-	ns	1,4
W3	t_{WP}	R-WE# (S-CS1#) Pulse Width	55	-	ns	1,2,3
W4	t_{DW}	Data to Write Time Overlap	30	-	ns	1
W5	t_{AW}	Address Setup to R-WE# (S-CS1#) High	60	-	ns	1
W6	t_{CW}	S-CS1# (R-WE#) Setup to R-WE# (S-CS1#) High	60	-	ns	1
W7	t_{DH}	Data Hold from R-WE# (S-CS1#) High	0	-	ns	1
W8	t_{WR}	Write Recovery	0	-	ns	1,5
W9	t_{BW}	R-UB#, R-LB# Setup to R-WE# (S-CS1#) High	60	-	ns	1

Notes:

1. See **Figure 6, "AC Waveform SRAM Write Operations"**.
2. A write occurs during the overlap (t_{WP}) of low S-CS1# and low R-WE#. A write begins when S-CS1# goes low and R-WE# goes low with asserting R-UB# and R-LB# for single byte operation or simultaneously asserting R-UB#R-LB# and R-LB# for double byte operation. A write ends at the earliest high transition of S-CS1# and R-WE#.
3. t_{WP} is measured from S-CS1# low to the end of a write.
4. t_{AS} is measured from the address valid to the beginning of a write.
5. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as S-CS1# or R-WE# goes high.

Figure 6: AC Waveform SRAM Write Operations



7.3 PSRAM AC Characteristics

Table 11: PSRAM AC Characteristics (85ns or 88ns Initial Access) – Read Operations

#	Symbol	Parameter ⁵	1.8 V		3.0 V		Unit	Notes
			Min	Max	Min	Max		
R1	t_{RC}	Read Cycle Time	88	4,000	85	4,000	ns	
R2	t_{AA}	Address to Output Delay	-	88	-	85	ns	
R3	t_{CO}	P-CS# to Output Delay	-	88	-	85	ns	

Table 11: PSRAM AC Characteristics (85ns or 88ns Initial Access) — Read Operations

#	Symbol	Parameter ⁵	1.8 V		3.0 V		Unit	Notes
			Min	Max	Min	Max		
R4	t_{OE}	R-OE# to Output Delay	-	65	-	40	ns	
R5	t_{BA}	R-UB#, R-LB# to Output Delay	-	88	-	85	ns	
R6	t_{LZ}	P-CS# to Output in Low-Z	10	-	10	-	ns	1,2
R7	t_{OLZ}	R-OE# to Output in Low-Z	5	-	0	-	ns	2
R8	t_{HZ}	P-CS# to Output in High-Z	-	25	0	25	ns	1,2,3
R9	t_{OHZ}	R-OE# to Output in High-Z	-	25	0	25	ns	2,3
R10	t_{OH}	Output Hold (from Address, P-CS# or R-OE# change, whichever occurs first)	5	-	0	-	ns	
R11	t_{BLZ}	R-UB#, R-LB# to Output in Low-Z	5	-	0	-	ns	2
R12	t_{BHZ}	R-UB#, R-LB# to Output in High-Z	-	25	0	25	ns	2
PR1	t_{PC}	Page Cycle Time	30	-	40	-	ns	4
PR2	t_{PA}	Page Access Time	-	30	-	35	ns	4

Note:

1. At any given temperature and voltage condition, t_{HZ} (Max) is less than t_{LZ} (Max) both for a given device and from device to device interconnection.
2. Sampled but not 100% tested.
3. Timings of t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
4. 4-Word Page read only available for 32-Mbit PSRAM. No page mode feature for 16-Mbit PSRAM.
5. Applicable to parts with 85ns or 88ns initial access time: 38F2030W0ZxQ1, 38F2040W0YxQ0, 38F2040W0ZxQ0, 28F2240W0YxQ0.

Table 12: PSRAM AC Characteristics (70ns Initial Access) – Read Operations

#	Symbol ¹	Parameter ⁷	1.8 V		3.0 V		Unit	Notes
			Min	Max	Min	Max		
R1	t _{RC}	Read Cycle Time	70	15000	70	15000	ns	2
			70	8000	-	-		
R2	t _{AA}	Address to Output Delay	-	70	-	70	ns	
R3	t _{CO}	P-CS# to Output Delay	-	70	-	70	ns	
R4	t _{OE}	R-OE# to Output Delay	-	45	-	45	ns	
R5	t _{BA}	R-UB#, R-LB# to Output Delay	-	70	-	70	ns	
R6	t _{LZ}	P-CS# to Output in Low-Z	5	-	5	-	ns	3
R7	t _{OLZ}	R-OE# to Output in Low-Z	0	-	0	-	ns	
R8	t _{HZ}	P-CS# to Output in High-Z	0	25	0	25	ns	3, 4
R9	t _{OHZ}	R-OE# to Output in High-Z	0	25	0	25	ns	4
R10	t _{OH}	Output Hold (from Address, P-CS# or R-OE# change, whichever occurs first)	0	-	0	-	ns	
R11	t _{BLZ}	R-UB#, R-LB# to Output in Low-Z	0	-	0	-	ns	
R12	t _{BHZ}	R-UB#, R-LB# to Output in High-Z	0	25	0	25	ns	
PR1	t _{PC}	Page Cycle Time	25	-	25	-	ns	5
PR2	t _{PA}	Page Access Time	-	25	-	25	ns	5
	t _{CEL}	CE# low-time restriction	-	8,000	ns	4	ns	6

Note:

- See Figure 7, "AC Waveform of PSRAM Read Operations" on page 25 and Figure 8, "AC Waveform of PSRAM 4-Word Page Read Operation" on page 25
- Spec's only applicable to parts 38F1030W0YxQF & 38F2030W0YxQF
- At any given temperature and voltage condition, t_{HZ} (Max) is less than t_{LZ} (Max) both for a given device and from device to device interconnection.
- Timings of t_{HZ} and t_{OHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referenced to output voltage levels.
- 4-Word Page read only available for 16-Mbit PSRAM. No page mode feature for 8-Mbit PSRAM. Parts 38F1030W0YxQF & 38F2030W0YxQF do not support page mode, so this spec will not apply to them
- CE# must go high and be maintained high for a minimum of 10ns at least once every 8,000ns
- Applicable to 70ns initial access P-SRAM's (38F1030W0YxQ2, 38F1030W0ZxQ0, 38F2030W0YxQ1, 38F2030W0YxQ2, 38F2030W0YxQF, 38F2030W0ZxQ2)

Figure 7: AC Waveform of PSRAM Read Operations

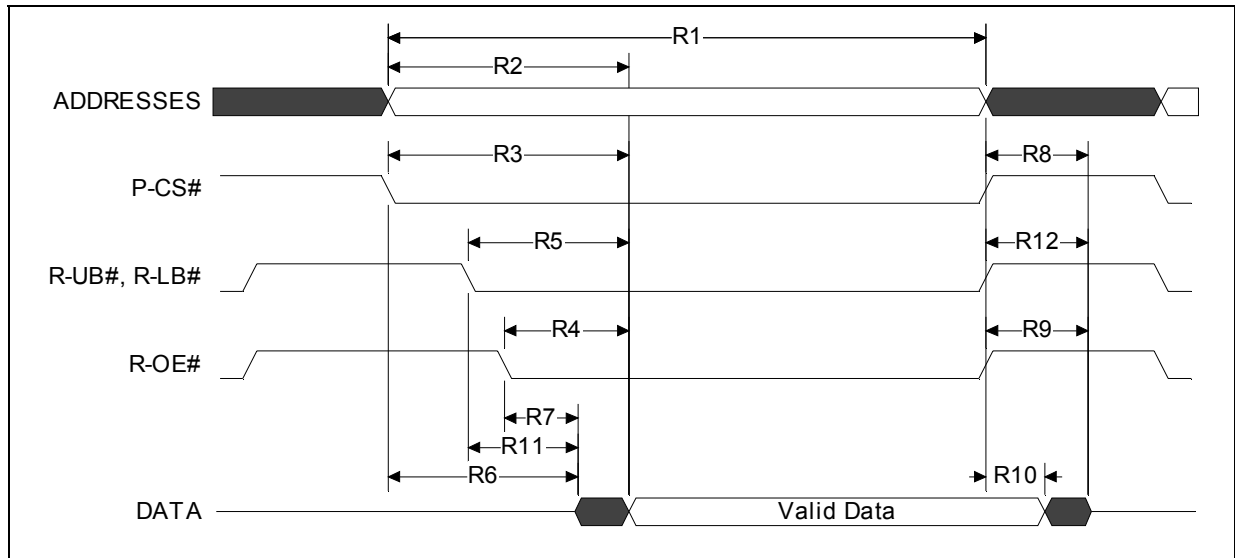
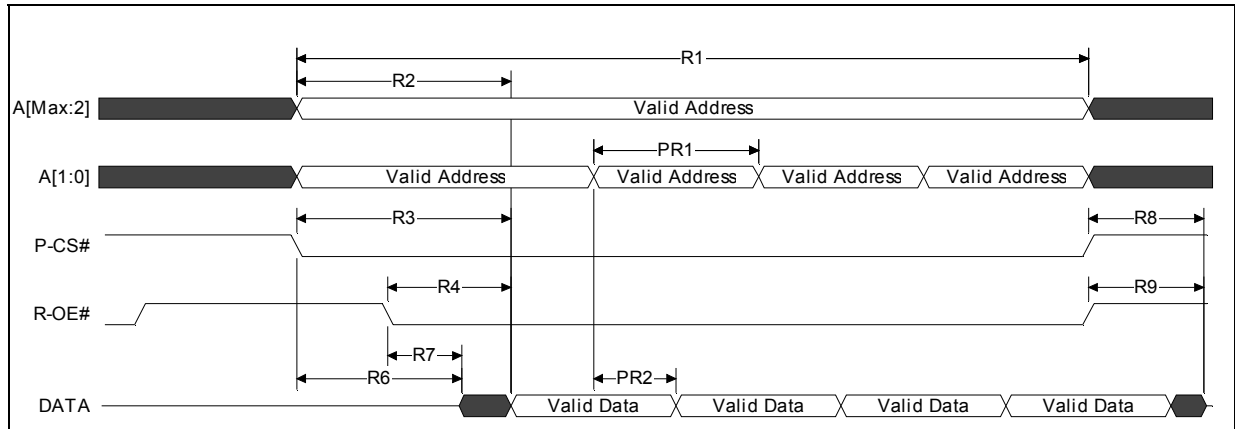


Figure 8: AC Waveform of PSRAM 4-Word Page Read Operation



Note: Available only for 32-Mbit PSRAM and line items with 16-Mbit PSRAM (70 ns) 38F2030W0YTQ1, 38F2030W0YBQ1, 38F2030W0ZTQ2, 38F2030W0ZBQ2, 38F1030W0ZTQ0, 38F1030W0ZBQ0. Not applicable to 8-Mbit PSRAM.

Table 13: PSRAM AC Characteristics—Write (Sheet 1 of 2)

#	Symbol ¹	Parameter ⁷	1.8 V		3.0 V		Unit	Notes
			Min	Max	Min	Max		
W1	t_{WC}	Write Cycle Time	70	8000	70	-	ns	
W2	t_{AS}	Address Setup to R-WE# (P-CS#) and R-UB#, R-LB# going low	0	-	0	-	ns	4
W3	t_{WP}	R-WE# (P-CS#) Pulse Width	55	-	55	-	ns	2,3
W4	t_{DW}	Data to Write Time Overlap	35	-	35	-	ns	

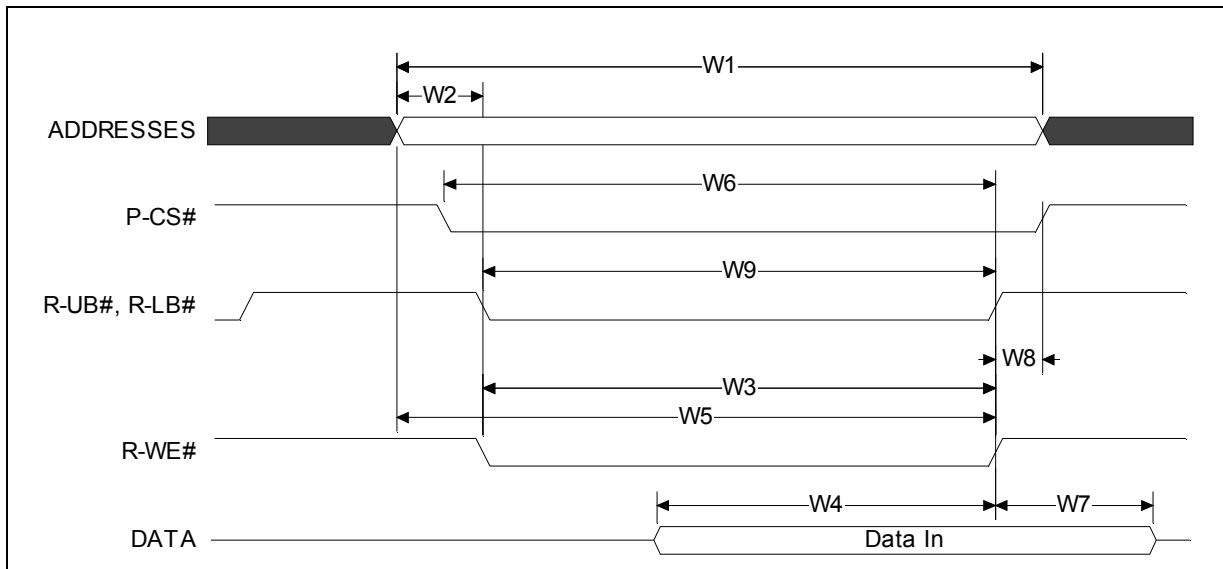
Table 13: PSRAM AC Characteristics—Write (Sheet 2 of 2)

#	Symbol ¹	Parameter ⁷	1.8 V		3.0 V		Unit	Notes
			Min	Max	Min	Max		
W5	t_{AW}	Address Setup to R-WE# (P-CS#) Going High	60	-	60	-	ns	
W6	t_{CW}	P-CS# (R-WE#) Setup to R-WE# (P-CS#) Going High	60	-	60	-	ns	
W7	t_{DH}	Data Hold from R-WE# (P-CS#) High	0	-	0	-	ns	
W8	t_{WR}	Write Recovery	0	-	0	-	ns	5
W9	t_{BW}	R-UB#, R-LB# Setup to R-WE# (P-CS#) Going High	60	-	60	-	ns	
	t_{CEL}	P-CE# low-time restriction	-	8,000	-	-	ns	7,8
W10	t_{WPH}	Write High Pulse Width	10	-	-	-	ns	8

Notes:

1. See **Figure 9, "AC Waveform PSRAM Write Operation"**.
2. A write occurs during the overlap (t_{WP}) of low P-CS# and low R-WE#. A write begins when P-CS# goes low and R-WE# goes low with asserting R-UB# or R-LB# for single byte operation or simultaneously asserting R-UB# and R-LB# for double byte operation. A write ends at the earliest transition when P-CS# goes high and R-WE# goes high.
3. t_{WP} is measured from P-CS# going low to end of a write.
4. t_{AS} is measured from the address valid to the beginning of a write.
5. t_{WR} is measured from the end of a write to the address change. t_{WR} applied in case a write ends as P-CS# or R-WE# going high.
6. W3 is 70 ns for continuous write operations over 50 times.
7. P-CE# must go high and be maintained high for a minimum of 10ns at least once every 8,000ns
8. Spec's only applicable to parts 38F1030W0YxQF & 38F2030W0YxQF
9. Applicable to 38F2020W0ZTQ1, 38F2020W0ZBQ1, 38F2030W0YTQ1, 38F2030W0YBQ1, 38F2030W0ZTQ2, 38F2030W0ZBQ2, 38F1030W0ZTQ0, 38F1030W0ZBQ0.

Figure 9: AC Waveform PSRAM Write Operation



7.4 Device AC Test Conditions

Figure 10: Transient Input/Output Reference Waveform

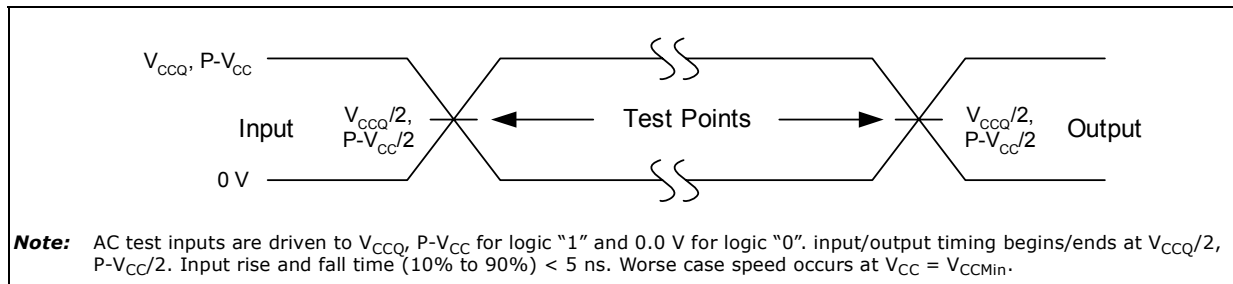
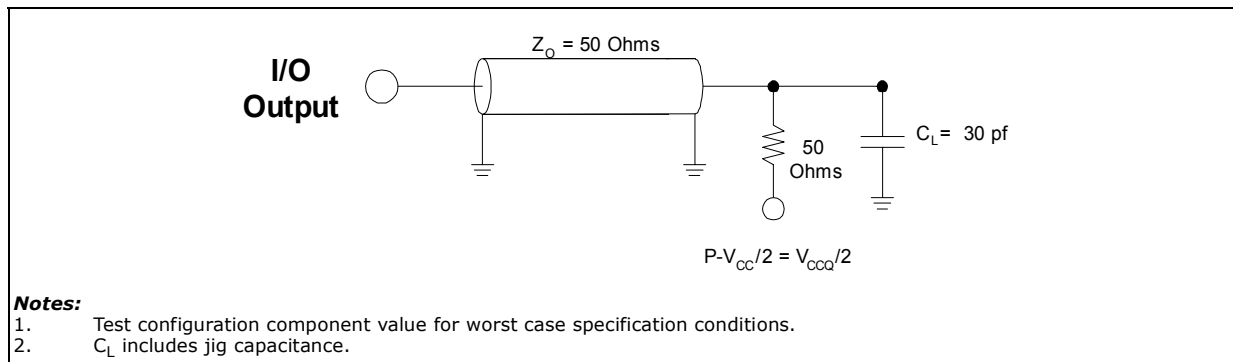


Figure 11: Transient Equivalent Testing Load Circuit



8.0 Flash Power Consumption

Refer to the Numonyx Wireless Flash Memory (W18) Datasheet (order number 290701) and Numonyx Wireless Flash Memory (W30) Datasheet (order number 290702) for detailed information.

9.0 Device Operation

9.1 Bus Operations

Bus operations for the W18/W30 SCSP family involve the following chip enable and output enable signals, respectively:

- F1-CE# for Flash Die#1 and F2-CE# for Flash Die#2
- F1-OE# for Flash Die#1 and F2-OE# for Flash Die#2

All other control signals are shared between the two flash die. [Table 14](#) to [Table 16](#) explain the bus operations of products across this SCSP family. Refer to the W18/W30 discrete datasheets (order numbers 290701 and 290702) for single flash die SCSP bus operations.

Table 14: Flash-Only Bus Operations

Device	Mode	F-RST#	F1-CE#	F1-OE#	F-WE#	ADV#	F-VPP	WAIT	F2-CE#	F2-OE#	D[15:0]	Notes
Flash Die#1	Sync Array Read	H	L	L	H	L	X	Active	H	X	Flash D _{OUT}	2, 3, 4
	All Async / Sync Non-Array Read	H	L	L	H	X	X	Asserted	H	X	Flash D _{OUT}	1, 3, 4, 5
	Write	H	L	H	L	X	V _{PPL} OR V _{PPH}	Asserted	H	X	Flash D _{IN}	3, 4, 6
	Output Disable	H	L	H	H	X	X	Active	X	X	Flash High-Z	4
	Standby	H	H	X	X	X	X	High-Z	X	X	Flash High-Z	4
	Reset	L	X	X	X	X	X	High-Z	X	X	Flash High-Z	4

Table 14: Flash-Only Bus Operations

Device	Mode	F-RST#	F1-CE#	F1-OE#	F-WE#	ADV#	F-VPP	WAIT	F2-CE#	F2-OE#	D[15:0]	Notes
Flash Die# 2	Sync Array Read	H	H	X	H	L	X	Active	L	L	Flash D _{OUT}	2, 3, 4
	All Async / Sync Non-Array Read	H	H	X	H	X	X	Asserted	L	L	Flash D _{OUT}	1, 3, 4, 5
	Write	H	H	X	L	X	V _{PPL} or V _{PPH}	Asserted	L	H	Flash D _{IN}	3, 4, 6
	Output Disable	H	X	X	H	X	X	Active	L	H	Flash High-Z	4
	Standby	H	X	X	X	X	X	High-Z	H	X	Flash High-Z	4
	Reset	L	X	X	X	X	X	High-Z	X	X	Flash High-Z	4

Notes:

- For asynchronous read operation, both die may be simultaneously selected, but may not simultaneously drive the memory bus. See [Section 10.0, "Flash Command Definitions" on page 33](#) for details regarding flash selection overlap.
- WAIT is only valid during synchronous flash reads. WAIT is driven if F-CE# is asserted. Refer to the W18 or W30 datasheet (order number 290701 and 29702) for further information regarding WAIT Signal.
- For either flash die, F[2:1]-OE# and F-WE# should never be asserted simultaneously. If done so on a particular flash die, F[2:1]-OE# will override F-WE#.
- L means V_{IL} while H means V_{IH}. X can be V_{IL} or V_{IH} for inputs, V_{PPL}, V_{PPH} or V_{PPLK} for F-VPP.
- Flash CFI query and status register accesses use D[7:0] only, all other reads use D[15:0].
- Refer to W18/W30 datasheet for valid D_{IN} during flash writes.

Table 15: Flash + SRAM Bus Operations

Device	Mode	F-RST#	F[2:1]-CE#	F[2:1]-OE#	F-WE#	ADV#	F-VPP	WAIT	S-CS1#	S-CS2	R-OE#	R-WE#	R-UB#, R-LB#	D[15:0]	Notes
Flash Die (#1 or #2)	Sync Array Read	H	L	L	H	L	X	Active	SRAM must be in High-Z					Flash D _{OUT}	1, 2, 3, 5
	All Async/ Sync Non-array Read	H	L	L	H	X	X	Asserted						Flash D _{OUT}	1, 2, 3, 5, 6
	Write	H	L	H	L	L	V _{PPL} or V _{PPH}	Asserted						Flash D _{IN}	3, 7
	Output Disable	H	L	H	H	X	X	Active	Any SRAM mode allowed					Flash High-Z	5
	Standby	H	H	X	X	X	X	High-Z						Flash High-Z	5
	Reset	L	X	X	X	X	X	High-Z						Flash High-Z	5

Table 15: Flash + SRAM Bus Operations

Device	Mode	F-RST#	F[2:1]-CE#	F[2:1]-OE#	F-WE#	ADV#	F-VPP	WAIT	S-CS1#	S-CS2	R-OE#	R-WE#	R-UB#, R-LB#	D[15:0]	Notes	
SRAM	Read	Flash must be in High-Z								L	H	L	H	L	SRAM D _{OUT}	1, 4, 8, 2
	Write									L	H	X	L	L	SRAM D _{IN}	4, 5, 8, 2
	Output Disable									L	H	H	H	X	SRAM High-Z	5, 2
	Standby	Any flash mode allowed								H	X	X	X	X	SRAM High-Z	5, 8, 2
										X	L					
Data Retention									Same as SRAM standby					SRAM High-Z	9, 2	

Notes:

1. For asynchronous read operation, all die may be simultaneously selected, but may not simultaneously drive the memory bus.
2. WAIT is only valid during synchronous flash reads. WAIT is driven if F-CE# is asserted.
3. For flash die, F[2:1]-OE# and F-WE# should never be asserted simultaneously. If done so, F[2:1]-OE# will override F-WE#.
4. For SRAM, R-OE# and R-WE# should never be asserted simultaneously.
5. X can be V_{IL} or V_{IH} for inputs, V_{PPL}, V_{PPH} or V_{PPLK} for F-VPP.
6. Flash CFI query and status register accesses use D[7:0] only, all other reads use D[15:0].
7. Refer to W18 and W30 datasheet for valid D_{IN} during flash writes.
8. The SRAM is enabled and/or disabled with the logical function: S-CS1# OR S-CS2.
9. The SRAM can be placed into data retention mode by lowering S-VCC to the V_{DR} limit when in standby mode.

Table 16: Flash + PSRAM Bus Operations

Device	Mode	F-RST#	F[2:1]-CE#	F[2:1]-OE#	F-WE#	ADV#	F-VPP	WAIT	P-CS#	P-Mode	R-OE#	R-WE#	R-UB#, R-LB#	D[15:0]	Notes
Flash Die(#1 or #2)	Sync Array Read	H	L	L	H	L	X	Active	PSRAM must be in High-Z					Flash D _{OUT}	1, 2, 3, 4, 6
	All Async/ Sync Non- array Read	H	L	L	H	X	X	Asserted						Flash D _{OUT}	1, 2, 3, 4, 6, 7
	Write	H	L	H	L	X	V _{PPL} OR V _{PPH}	Asserted						Flash D _{IN}	3, 4, 6, 8
	Output Disable	H	L	H	H	X	X	Active	Any PSRAM mode allowed					Flash High-Z	6
	Standby	H	H	X	X	X	X	High-Z						Flash High-Z	6
	Reset	L	X	X	X	X	X	High-Z						Flash High-Z	6

Table 16: Flash + PSRAM Bus Operations

Device	Mode	F-RST#	F[2:1]-CE#	F[2:1]-OE#	F-WE#	ADV#	F-VPP	WAIT	P-CS#	P-Mode	R-OE#	R-WE#	R-UB#/ R-LB#	D[15:0]	Notes
PSRAM	Read	Flash#1 and #2 must be in High-Z							L	H	L	H	L	PSRAM D _{OUT}	1, 5, 2
	Write	Flash#1 and #2 must be in High-Z							L	H	H	L	L	PSRAM D _{IN}	5, 2
	Output Disable	Any flash mode allowed							L	H	H	H	X	PSRAM High-Z	6, 2
	Standby	Any flash mode allowed							H	H	X	X	X	PSRAM High-Z	6, 2
	Deep Power-Down	Any flash mode allowed							H	L	X	X	X	PSRAM High-Z	6, 9, 2

Notes:

1. For asynchronous read operation, all die may be simultaneously selected, but may not simultaneously drive the memory bus. For synchronous burst-mode reads, only two die (one flash and the PSRAM) may be simultaneously selected.
2. WAIT is only valid during synchronous flash reads. WAIT is driven if F-CE# is asserted.
3. F1-CE# for Flash Die#1, F2-CE# for Flash Die#2. F1-OE# is for Flash Die#1, F2-OE# for Flash Die#2.
4. For either flash die, F[2:1]-OE# and F-WE# should never be asserted simultaneously. If done so on a particular flash die, F[2:1]-OE# will override F-WE#.
5. For PSRAM, R-OE# and R-WE# should never be asserted simultaneously.
6. X can be V_{IL} or V_{IH} for inputs, V_{PPL}, V_{PPH} or V_{PPLK} for F-VPP.
7. Flash CFI query and status register accesses use D[7:0] only, all other reads use D[15:0].
8. Refer to W30/W18 datasheet for Valid D_{IN} during flash writes.
9. Deep power-down is not applicable to 38F2020W0ZTQ1, 38F2020W0ZBQ1, 38F2030W0YTQ1, 38F2030W0YBQ1, 38F2030W0ZTQ2, 38F2030W0ZBQ2, 38F1030W0ZTQ0, 38F1030W0ZBQ0.

10.0 Flash Command Definitions

Refer to the Numonyx Wireless Flash Memory (W18) Datasheet (order number 290701) and Numonyx Wireless Flash Memory (W30) Datasheet (order number 290702) for detailed information regarding the following:

11.0 Flash Read Operations

12.0 Flash Program Operations

13.0 Flash Erase Operations

14.0 Flash Security Modes

15.0 Flash Read Configuration Register

16.0 SRAM Operations

16.1 Power-up Sequence and Initialization

The SRAM functionality and reliability are independent of the power-up sequence and power-up slew rate of the core S-V_{CC}. Any power-up sequence and power-up slew rate is possible under use conditions. SRAM reliability is also independent of the power-down sequence and power-down slew rate of the core S-V_{CC}.

16.2 Data Retention Mode

Table 17: SRAM Data Retention Operation

Symbol	Parameter	Min	Max	Unit	Notes
t _{SDR}	Data Retention Set-up Time	0	-	ns	
t _{RDR}	Data Retention Recovery Time	t _{RC}	-	ns	1

Note:

- t_{RC} is defined in [Table 9, "SRAM AC Characteristics"](#) on page 20.

Figure 12: SRAM Data Retention Operation Waveform—S-CS1# Controlled

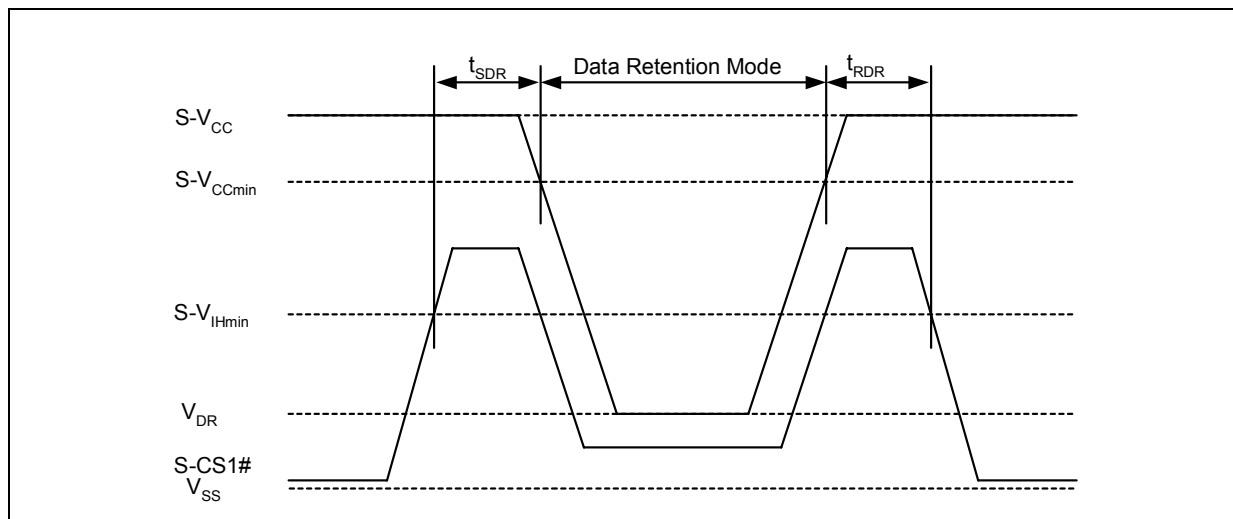
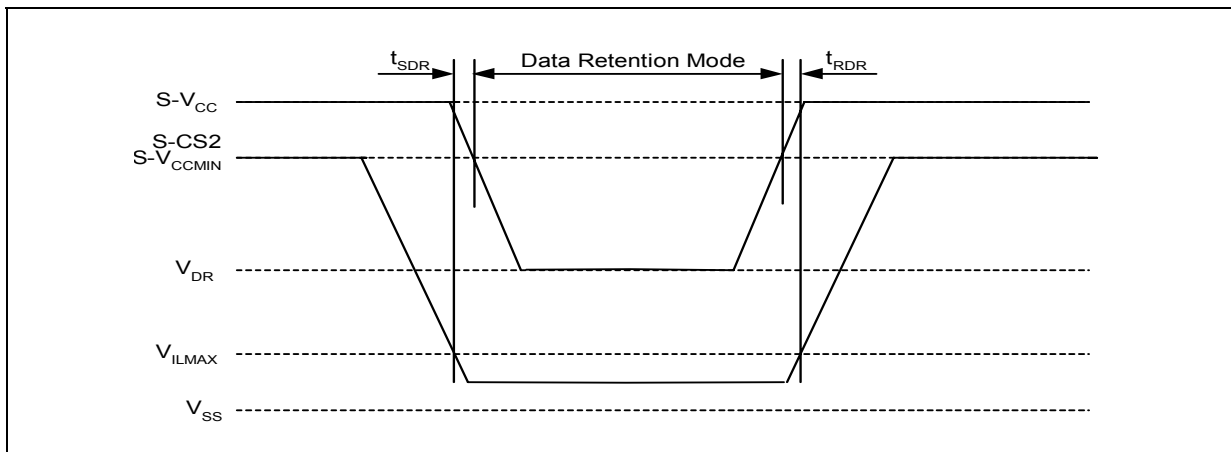


Figure 13: SRAM Data Retention Operation Waveform—S-CS2 Controlled



17.0 PSRAM Operations

17.1 Power-Up Sequence and Initialization

The PSRAM functionality and reliability are independent of the power-up sequence and slew rate of the core P-V_{CC}. Any power-up sequence and slew rate is possible under use conditions. PSRAM reliability are also independent of the power-down sequence and slew rate of the core P-V_{CC}.

The following power-up sequence and register setting should be used before starting normal operation. The PSRAM power-up sequence is represented in Figure 14. Following power application, make P-Mode high after fixing P-Mode to a low level for a period of t_{11} . Make P-CS# high before making P-Mode high. P-CS# and P-Mode are fixed to a high level for period of t_{13} .

Figure 14: Timing Waveform for Power-Up Sequence

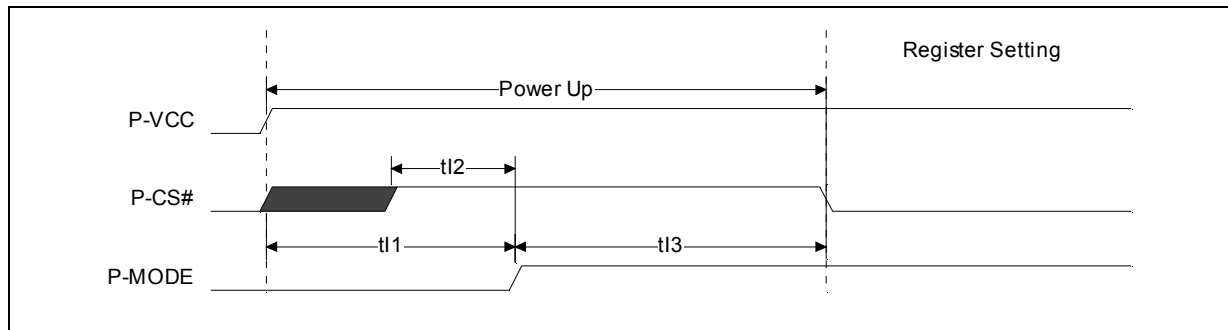


Table 18: Power-Up Sequence Specifications

Parameter	Description	Min	Max	Unit	Notes
t_{11}	Power application with P-Mode held low	50	—	μ s	1,2,3
t_{12}	P-CS# high to P-Mode high	10	—	ns	
t_{13}	P-Mode high to P-CS# low	500	—	μ s	

Notes:

1. Toggle P-Mode to low when starting the power-up sequence.
2. t_{11} is specified from when the power supply voltage reaches V_{CCMIN} .
3. Does not apply to 38F2020W0ZTQ1, 38F2020W0ZBQ1, 38F2030W0YTQ1, 38F2030W0YBQ1, 38F2030W0ZTQ2, and 38F2030W0ZBQ2, 38F1030W0ZTQ0, 38F1030W0ZBQ0 line items. Valid PSRAM operations for these line items can begin 200 μ s after P-Vcc has reached P-Vcc min.

17.1.1 16Mbit PSRAM Power-Up Sequence (Non-Page Mode)

For the non-page mode PSRAM (part's RD38F1030W0YQF, PF38F1030W0YQF, RD38F2030W0YQF, PF38F2030W0YQF) the PSRAM functionality and reliability must be independent of the power-up sequence and power-up slew rate of the core Vcc and the I/O Vcc (Vccq.) Any power-up sequence and power-up slew rate is possible under use conditions. PSRAM reliability must also be independent of the power-down sequence and power-down slew rate of the core Vcc and the I/O Vcc (Vccq.)

Once power supply voltages have reached the minimum spec value of 1.7V (or higher), CE# must be maintained high for minimum 200us prior to commencing valid PSRAM operation.

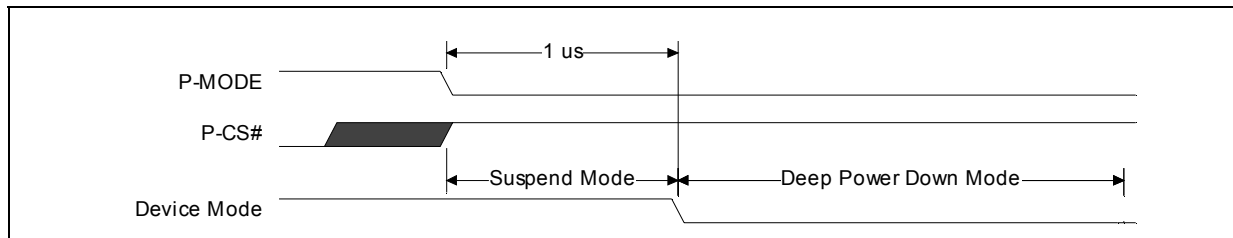
17.2 Standby Mode/ Deep Power-Down Mode

Caution: All line items that do not have the P-Mode pine will not have the deep power-down feature (38F1030W0YxQ2, 38F1030W0ZxQ0, 38F2030W0YxQ1, 38F2030W0YxQ2, 38F2030W0YxQF, 38F2030W0ZxQ2, 38F2040W0ZxQ0).

Data is lost during deep power-down mode as shown in the Table below. Wake-up from deep power-down mode involves the same initialization sequence as discussed in [Section 17.1, "Power-Up Sequence and Initialization"](#) on page 36.

Mode	Memory Cell Data	Delay time to go Active
Standby	Valid	0 ns
Deep Power-Down	Invalid	Start-Up Sequence

Figure 15: Timing Waveform for Entering Deep Power-Down Mode



17.3 PSRAM Special Read and Write Constraints

Caution: This section will not apply to line items that do not have the P-Mode pine will not have the deep power-down feature (38F1030W0YxQ2, 38F1030W0ZxQ0, 38F2030W0YxQ1, 38F2030W0YxQ2, 38F2030W0YxQF, 38F2030W0ZxQ2, 38F2040W0ZxQ0).

Table 19: PSRAM Special Read Constraints

Description	Min	Max	Unit	Notes
Cannot have sub t_{RC} address toggle for more than 4 μ s in active mode. Need either a read operation or P-CS# high for t_{RC} in that time frame	N/A	N/A	-	
P-CS# high level pulse width	10	-	ns	1
R-UB#/R-LB# high level pulse width	10	-	ns	1
R-OE# high level pulse width in active mode (P-CS# low)	10	10,000	ns	
P-CS# low to R-OE# low	-	10,000	ns	
Address Skew time (unstable address with P-CS# low)	-	10	ns	2

Notes:

1. Toggling of these control signals is not necessary during address controlled read operations.
2. Address skew time (t_{SKEW}) indicates the following three types of time depending on the condition.
 - a. When switching P-CS# from high to low, t_{SKEW} is the time from the P-CS# low input point until the next address is determined.
 - b. When switching P-CS# from low to high, t_{SKEW} is the time from the address change start point to the P-CS# high input point.
 - c. When P-CS# is fixed to low, t_{SKEW} is the time from the address start point until the next address is determined. Since specs are defined for t_{SKEW} only when P-CS# is active, t_{SKEW} is not subject to limitations when P-CS# is switched from high to low following address determination, or when the address is changed after P-CS# is switched from low to high.

Table 20: PSRAM Special Write Constraints

Description	Min	Max	Unit	Notes
Need either R-WE# high or P-CS# high for at least t_{WC} time, for every 4us window during write operations.	N/A	N/A	-	
R-OE# high to R-WE# low in active mode (P-CS# low)	0	10,000	ns	
R-WE# high to R-OE# low in active mode (P-CS# low)	10	10,000	ns	
Address Skew time (unstable address with P-CS# low)	-	10	ns	1

Note:

1. Address skew time (t_{SKEW}) indicates the following three types of time depending on the condition.
 - a. When switching P-CS# from high to low, t_{SKEW} is the time from the P-CS# low input point until the next address is determined.
 - b. When switching P-CS# from low to high, t_{SKEW} is the time from the address change start point to the P-CS# high input point.
 - c. When P-CS# is fixed to low, t_{SKEW} is the time from the address start point until the next address is determined.

Since specs are defined for t_{SKEW} only when P-CS# is active, t_{SKEW} is not subject to limitations when P-CS# is switched from high to low following address determination, or when the address is changed after P-CS# is switched from low to high.

Appendix A Write State Machine

Refer to the *Numonyx Wireless Flash Memory (W18) Datasheet* (order number 290701) and *Numonyx Wireless Flash Memory (W30) Datasheet* (order number 290702) for the WSM details.

Appendix B Common Flash Interface

Refer to the *Numonyx Wireless Flash Memory (W18) Datasheet* (order number 290701) and *Numonyx™ Wireless Flash Memory (W30) Datasheet* (order number 290702) for the CFI details.

Appendix C Flash Flowcharts

Refer to the *Numonyx™ Wireless Flash Memory (W18) Datasheet* (order number 290701) and *Numonyx™ Wireless Flash Memory (W30) Datasheet* (order number 290702) for the flash flowchart details.

Appendix D Additional Information

Order Number	Document
290701	Numonyx™ Wireless Flash Memory (W18) Datasheet
290702	Numonyx™ Wireless Flash Memory (W30) Datasheet
251216	64-Mbit 1.8 Volt Numonyx™ Wireless Flash Memory SCSP Family Application Note

Note: Contact your local Numonyx or distribution sales office or visit the Numonyx website at <http://www.numonyx.com> for the most current information on Numonyx Flash memory products, software, and tools.

Appendix E Ordering Information (Active Line Items)

Figure 16: Decoder for Flash + RAM SCSP Family Devices

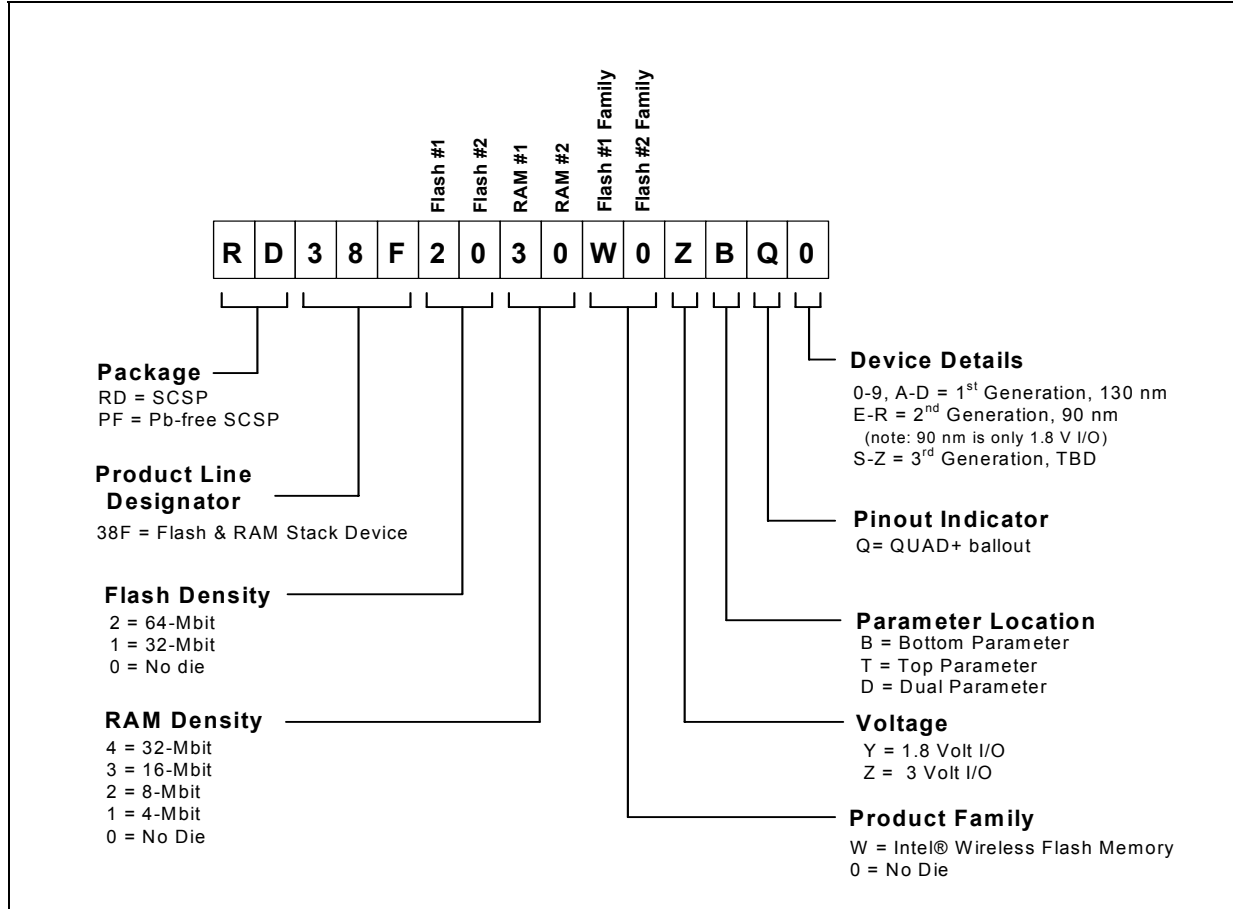


Table 21: Ordering Information on Active Line Items

Flash Component	RAM	Package			Product Number	PSRAM
Size in Mbit and Family	Size in Mbit and Type	Size (mm)	Ballout	Type		
32M Flash + 16M PSRAM						
32 W18	16 PSRAM	8 x 10 x 1.2	Quad+	Lead-free	PF38F1030W0YTQ2 PF38F1030W0YBQ2	70 ns, No PMODE pin & Non-Page Mode Support
	16 PSRAM				PF38F1030W0YTQF PF38F1030W0YBQF	
32 W30	16 PSRAM	8 x 10 x 1.2	Quad+	Lead-free	PF38F1030W0ZTQ0 PF38F1030W0ZBQ0	70 ns, No PMODE pin
64M Flash + 16M PSRAM						
64 W18	16 PSRAM	8 x 10 x 1.2	Quad+	Lead-free	PF38F2030W0YTQ1 PF38F2030W0YBQ1	70 ns, No PMODE pin
	16 PSRAM				PF38F2030W0YTQ2 PF38F2030W0YBQ2	70 ns, No PMODE pin & Non-Page Mode Support
					PF38F2030W0YTQF PF38F2030W0YBQF	
64 W30	16 PSRAM	8 x 10 x 1.2	Quad+	Lead-free	PF38F2030W0ZTQ2 PF38F2030W0ZBQ2	70 ns, No PMODE pin
64M Flash + 32M PSRAM						
64 W18	32 PSRAM	8 x 10 x 1.2	QUAD+	Lead-free	PF38F2040W0YTQ0 PF38F2040W0YBQ0	88 ns, with PMODE pin
64 W30	32 PSRAM	8 x 10 x 1.2	QUAD+	Lead-free	PF38F2040W0ZTQ1 PF38F2040W0ZBQ1	85 ns, No PMODE pin

Appendix F Ordering Information (Retired Line Items)

Shown here are the decoder for products in the SCSP family with both flash and RAM and the decoder for products in the SCSP family with flash die only (no RAM). The decoders are following by available product combinations.

Figure 17: Decoder for Flash + RAM SCSP Family Devices

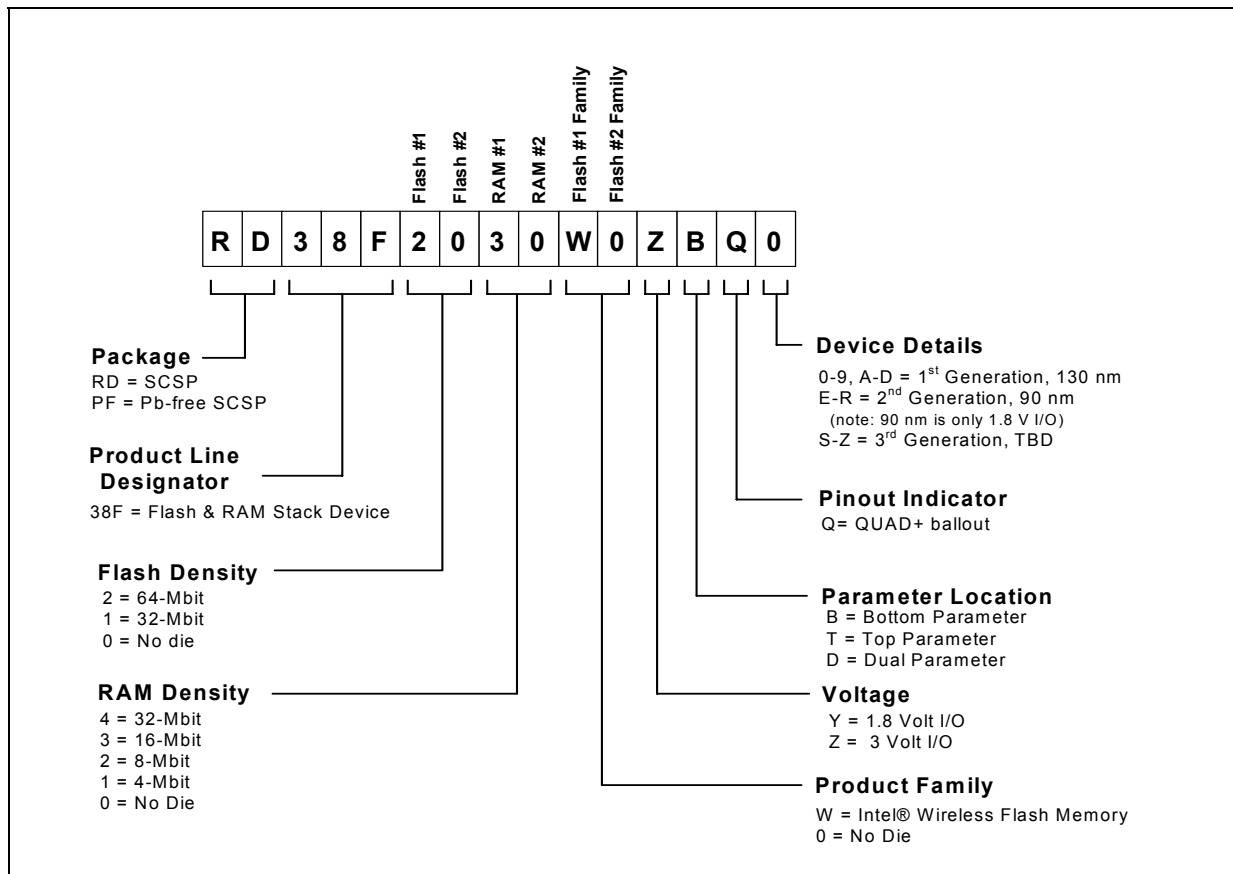


Figure 18: Decoder for Flash-Only SCSP Family Devices

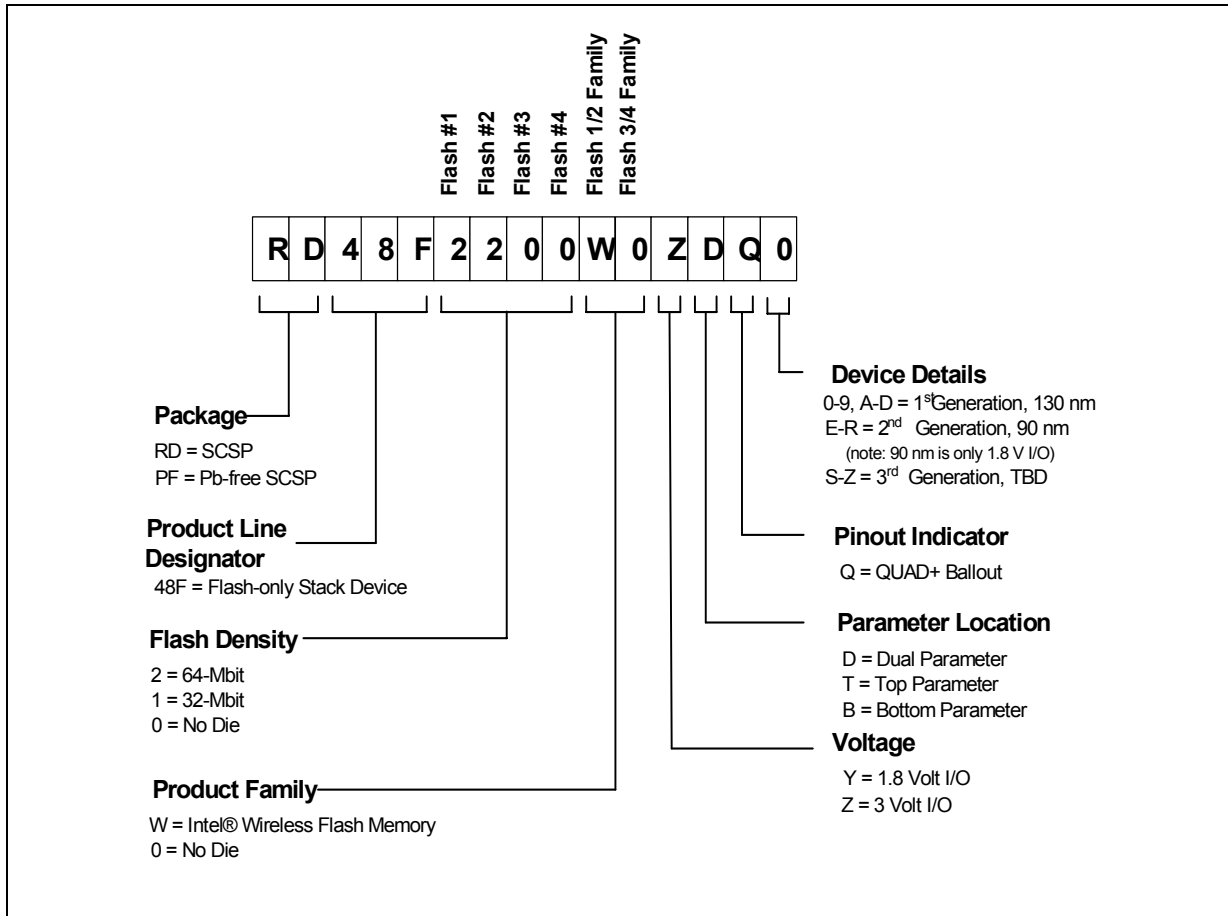


Table 22: 32WQ and 64WQ W18/W30 SCSP Ordering Information (Flash Only)

Flash Component	Package			Product Number ^(1,2,3,4,5)
	Size (mm)	Type	Ballout	
32 W30	8 x 10 x 1.2	Lead-free	Quad +	PF48F1000W0ZTQ0 PF48F1000W0ZBQ0
64 W30	8 x 10 x 1.2	Lead-free	Quad +	PF48F2000W0ZTQ0 PF48F2000W0ZBQ0
64 W18 + 64W18	8 x 10 x 1.2	Leaded	Quad +	RD48F2200W0YDQ0

Notes:

1. W18 = Numonyx™ Wireless Flash Memory (W18); W30 = Numonyx™ Wireless Flash Memory (W30).
2. B = Bottom Parameter, where Flash Die #1, F1-CE# = Bottom Parameter and Flash Die #2, F2-CE# = Top Parameter.
3. T = Top Parameter where Flash Die #1, F1-CE# = Top Parameter and Flash Die #2, F2-CE# = Bottom Parameter.
4. D = Dual Parameter where Flash Die #1, F1-CE# = Bottom Parameter and Flash Die #2, F2-CE# = Top Parameter.

Table 23: 32WQ and 64WQ W18/W30 SCSP Ordering Information (Flash + SRAM)

Flash Component	RAM	Package			Product Number ^(1,2,3,4)
		Size (mm)	Type	Ballout	
64 W18	4 SRAM	8 x 10 x 1.2	Leaded	Quad+	RD38F2010W0YTQ0 RD38F2010W0YBQ0
	8 SRAM	8 x 10 x 1.2	Leaded	Quad+	RD38F2020W0YTQ0 RD38F2020W0YBQ0
	16 SRAM	8 x 10 x 1.2	Leaded	Quad+	RD38F2030W0YTQ0 RD38F2030W0YBQ0
64 W30	8 SRAM	8 x 10 x 1.2	Leaded	Quad+	RD38F2020W0ZTQ0 RD38F2020W0ZBQ0
	16 SRAM	8 x 10 x 1.2	Leaded	Quad+	RD38F2030W0ZTQ0 RD38F2030W0ZBQ0
64 W18 + 64 W18	16 SRAM	8 x 10 x 1.4	Leaded	Quad+	RD38F2230W0YDQ0
64 W30 + 64 W30	16 SRAM	8 x 10 x 1.4	Leaded	Quad+	RD38F2230W0ZDQ0

Notes:

1. W18 = Numonyx™ Wireless Flash Memory (W18); W30 = Numonyx™ Wireless Flash Memory (W30).
2. B = Bottom Parameter, where Flash Die #1, F1-CE# = Bottom Parameter and Flash Die #2, F2-CE# = Top Parameter.
3. T = Top Parameter where Flash Die #1, F1-CE# = Top Parameter and Flash Die #2, F2-CE# = Bottom Parameter.
4. D = Dual Parameter where Flash Die #1, F1-CE# = Bottom Parameter and Flash Die #2, F2-CE# = Top Parameter.

Table 24: 32WQ & 64WQ W18/W30 SCSP Ordering Information (Flash + PSRAM) (Sheet 1 of 2)

Flash Component	RAM	Package			Product Number (1,2,3,4,5)	PSRAM used
		Size (mm)	Ballout	Type		
32 W18	16 PSRAM	8 x 10 x 1.2	Quad+	Leaded	RD38F1030W0YTQ2 RD38F1030W0YBQ2	70 ns, No PMODE pin & Non-Page Mode Support
32 W30	16 PSRAM	8 x 10 x 1.2	Quad+	Leaded	RD38F1030W0ZTQ0 RD38F1030W0ZBQ0	70 ns, No PMODE pin
64 W18	16 PSRAM	8 x 10 x 1.2	Quad+	Leaded	RD38F2030W0YTQ1 RD38F2030W0YBQ1	70 ns, No PMODE pin
64 W18	16 PSRAM	8 x 10 x 1.2	Quad+	Leaded	RD38F2030W0YTQ2 RD38F2030W0YBQ2	70 ns, No PMODE pin & Non-Page Mode Support
64 W30	16 PSRAM	8 x 10 x 1.2	Quad+	Leaded	RD38F2030W0ZTQ1 RD38F2030W0ZBQ1	85 ns, with PMODE pin
64 W30	16 PSRAM	8 x 10 x 1.2	Quad+	Leaded	RD38F2030W0ZTQ2 RD38F2030W0ZBQ2	70 ns, No PMODE pin

Table 24: 32WQ & 64WQ W18/W30 SCSP Ordering Information (Flash + PSRAM) (Sheet 2 of 2)

Flash Component	RAM	Package			Product Number (1,2,3,4,5)	PSRAM used
		Size (mm)	Ballout	Type		
64 W18	32 PSRAM	8 x 10 x 1.2	QUAD+	Leaded	RD38F2040W0YTQ0 RD38F2040W0YBQ0	88 ns, with PMODE pin
64 W30	32 PSRAM	8 x 10 x 1.2	QUAD+	Leaded	RD38F2040W0ZTQ0 RD38F2040W0ZBQ0	85 ns, No PMODE pin
64 W30	32 PSRAM	8 x 10 x 1.2	QUAD+	Leaded	RD38F2040W0ZTQ1 RD38F2040W0ZBQ1	85 ns, No PMODE pin
64 W18 + 64 W18	32 PSRAM	8 x 10 x 1.4	QUAD+	Leaded	RD38F2240WWYDQ0 ⁽⁶⁾ RD38F2240WWYDQ1	88 ns, with PMODE pin
64 W30 + 64 W30	32 PSRAM	8 x 10 x 1.4	QUAD+	Leaded	RD38F2240WWZDQ0 RD38F2240WWZDQ1	85 ns, No PMODE pin

Notes:

1. W18 = Numonyx™ Wireless Flash Memory (W18); W30 = Numonyx™ Wireless Flash Memory (W30).
2. B = Bottom Parameter, where Flash Die #1, F1-CE# = Bottom Parameter and Flash Die #2, F2-CE# = Top Parameter.
3. T = Top Parameter where Flash Die #1, F1-CE# = Top Parameter and Flash Die #2, F2-CE# = Bottom Parameter.
4. D = Dual Parameter where Flash Die #1, F1-CE# = Bottom Parameter and Flash Die #2, F2-CE# = Top Parameter.
5. RD38F2240WWYDQ0 = Engineering Samples; RD38F2240WWYDQ1 = Production

32WQ and 64WQ Family with Asynchronous RAM